



Microcontroller for embedded space applications

TEC-ED & TEC-SW Final Presentation Day

Cobham Gaisler
December 2018

GR716 – LEON3FT Microcontroller

COBHAM

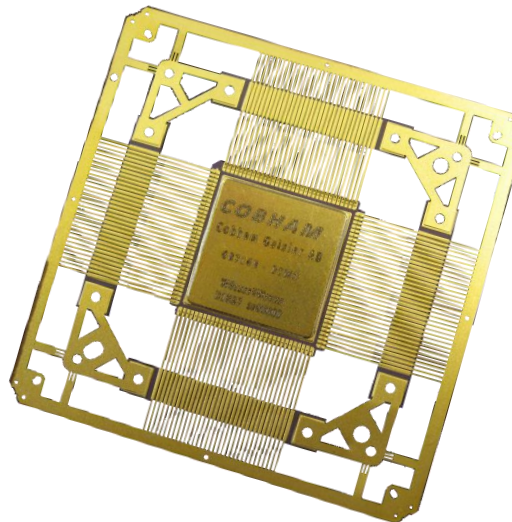
Microcontroller for embedded space applications

Objectives

The objectives of the activity are to define, design, manufacture and verify an ASIC containing the functionality of a mixed-signal microcontroller.

The device to be developed shall be easily accommodated in a large variety of platforms and payloads with moderate processing requirements, offering the possibility to distribute intelligence and I/O functionalities into the equipments, such as

- propulsion system control
- sensor bus control
- robotics applications control
- simple motor control
- mechanism control
- power control
- particle detector instrumentation
- radiation environment monitoring
- thermal control
- antenna pointing control
- remote terminal unit control
- simple instrument control



Project information

- Contract: 40001117749/14/NL/AK
- TO: Claudio Monteleone
- Project Start: February 2014 (KO)
- Project End: March 2019 (FR – Planned)
- Contractor: Cobham Gaisler
- Companies and organizations involved:



COBHAM
Cobham Gaisler AB

lmec

microcross

KYOCERA

PENDER
ELECTRONIC DESIGN

Microcontroller Introduction

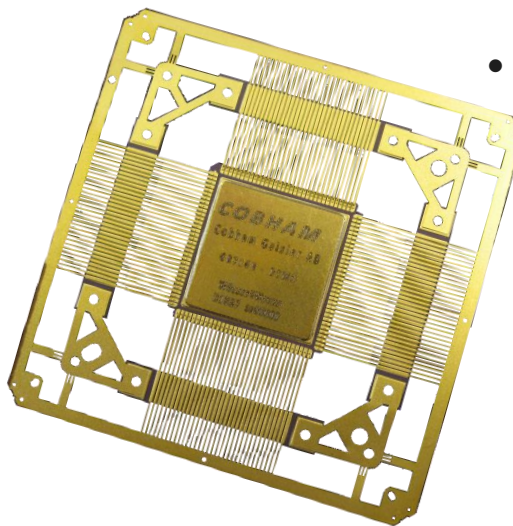
Description

The GR716 features a fault-tolerant LEON3 SPARC V8 processor, communication interfaces and on-chip ADC, DAC, Power-on-Reset, Oscillator, Brown-out detection, LVDS transceivers, regulators to support for single 3.3V supply, ideally suited for space and other high-rel applications

Applications

Support for many different standard interfaces makes the GR716 microcontroller is ideally fit for handling supervision and control in a satellite, such as

- propulsion system control
- sensor bus control
- robotics applications control
- simple motor control
- mechanism control
- power control
- particle detector instrumentation
- radiation environment monitoring
- thermal control
- antenna pointing control
- remote terminal unit control
- simple instrument control



Specifications

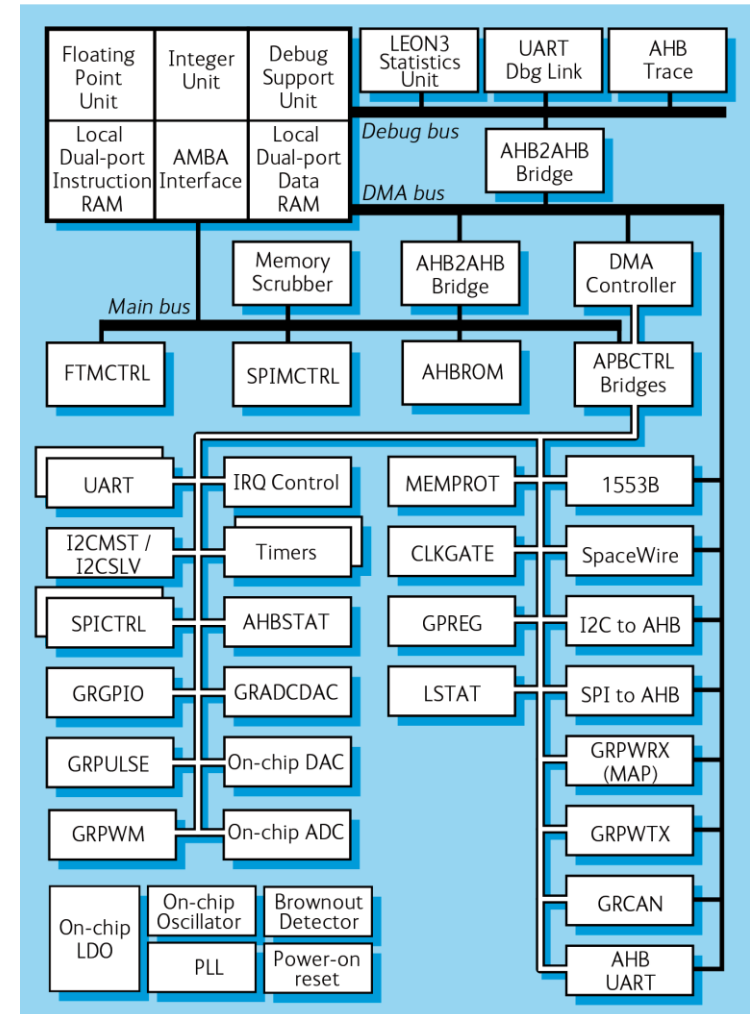
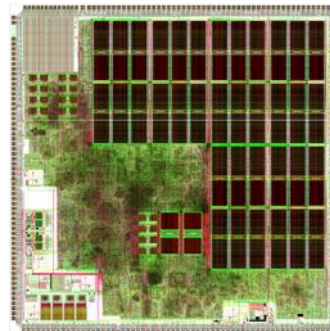
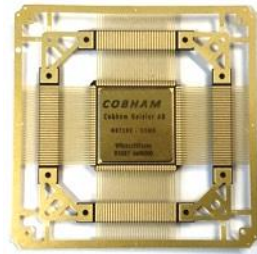
- System frequency up-to 50 MHz
- SpaceWire links up-to 100 Mbps
- CQFP132 hermetically sealed ceramic package
- Total Ionizing Dose (TID) up to 100 krad (Si, functional)
- Single-Event Latch-Up (SEL) to $LET_{TH} > 118 \text{ MeV-cm}^2\text{mg}$
- Single-Event Upset (SEU) below 10^{-12} bit error rate
- Support for single 3.3V supply



GR716 – LEON3FT Microcontroller

Microcontroller Features

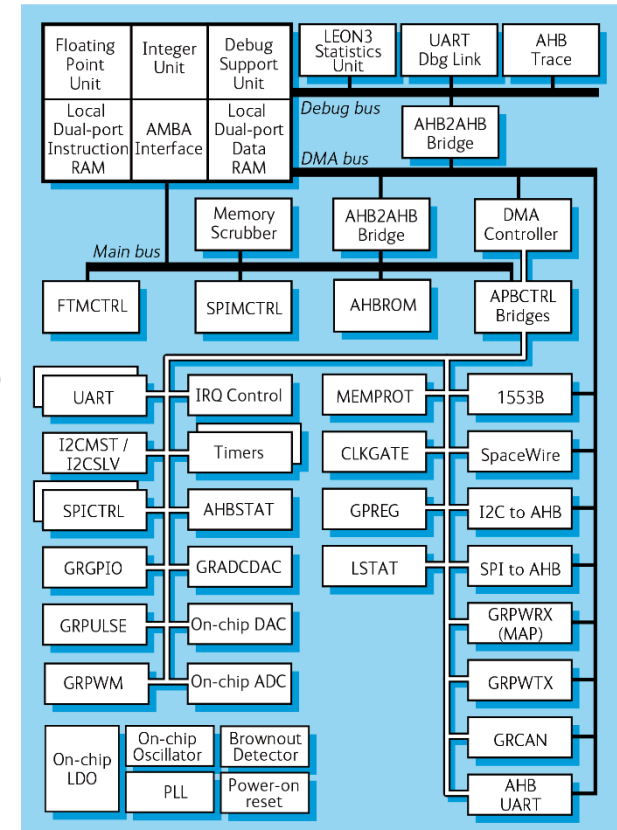
- LEON3FT - Fault-tolerant SPARC V8 32-bit processor, 50 MHz
 - 16-bit instruction set: LEON-REX - improved code density
 - Floating Point Unit
 - Memory protection units
 - Non-intrusive advanced on-chip debug support unit
- External EDAC memory: 8-bit PROM/SRAM, SPI, I2C
- SpaceWire interface with time distribution support, 100 Mbps
- MIL-STD-1553B interface
- 2x CAN 2.0B controller interface
- PacketWire with CRC acceleration support
- Programmable PWM interface
- SPI with SPI-for-Space protocols
- UARTs, I2C, GPIO, Timers with Watchdog
- Interrupt controller, Status registers, JTAG debug, etc.
- Dual ADC 11bits @ 200Ksps, 4 differential or 8 single ended
- DAC 12bits @ 3Msps, 4 channels
- Mixed General purpose inputs and outputs
- Power-on-Reset and Brown-out-detection
- Temperature sensor, Integrated PLL
- On-chip regulator for 3.3V single supply
- 132 pin QFP, 24 mm x 24 mm



GR716 – LEON3FT Microcontroller

Key features – system support

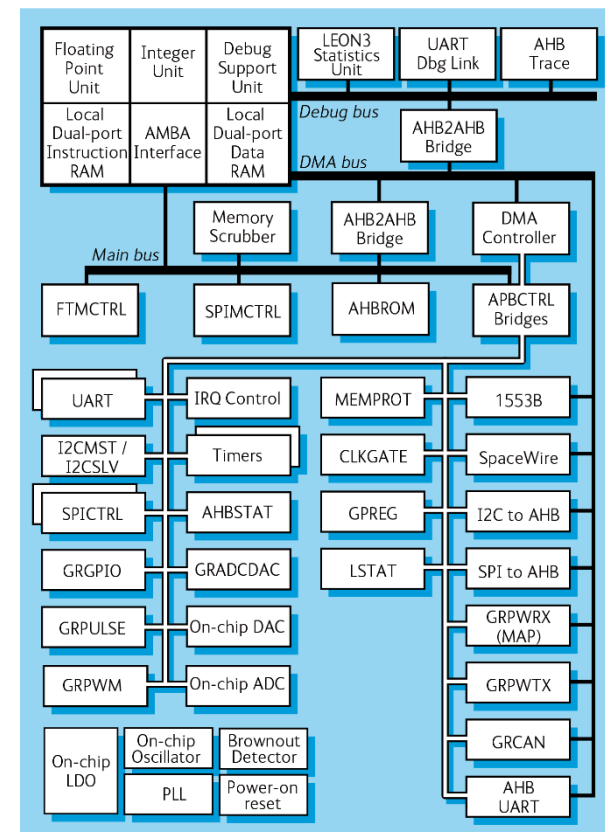
- On-chip voltage regulators for **single supply** support. Capability to sense core voltage for trimming of the embedded voltage regulator for low power applications.
- **Power-on-reset**, **Brownout** detection and Dual Watchdog for safe operation. External reset signal generation for companion chips.
- Crystal oscillator support and external clock reference
- One PLL for System and SpaceWire clock generation. In-application programming of system clock and peripheral clocks. System and SpaceWire clocks switches glitch free.
- **Low power mode** and individual clock gating of functions
- **Temperature** and core **voltage sensor**
- External voltage reference for precision measurement
- **Statistics** unit for **profiling** of the system



GR716 – LEON3FT Microcontroller

Key features - peripherals

- SpaceWire with RMAP and Time Distribution Protocol
- Redundant MIL-STD-1553B BRM (BC/RT/BM) interface
- Two CAN 2.0B bus controllers
- Six UART ports, with 16-byte FIFO
- Two SPI master/slave serial ports
- One SPI controller. Hardware support for SPI for Space slave
- Two I2C master/slave serial port
- PacketWire interface
- PWM with up-to 16 channels
- Up to 64 General input and outputs (GPIO) with external interrupt capability, pulse generation and sampling.
- 4x single ended Digital to Analog Converters (DAC), 12-bit at 3MS/s
- 4x differential or 8x single ended Analog to Digital Converters (ADC) dual sample and hold 11-bit at 200KS/s, with programmable pre-amplifier and support for oversampling
- External ADC and DAC support up to 16-bit at 1MS/s

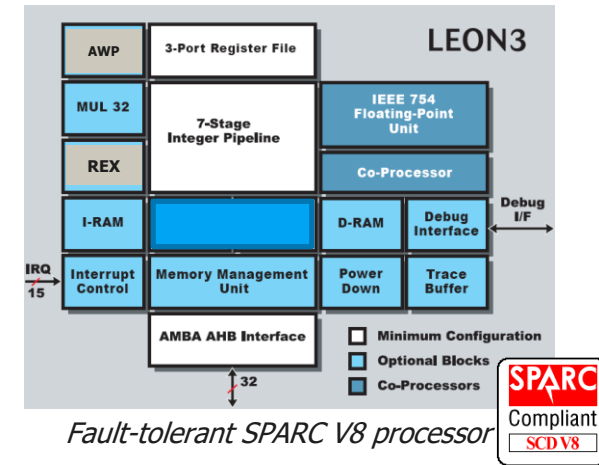


GR716 – LEON3FT Microcontroller

Key features – processor and memory

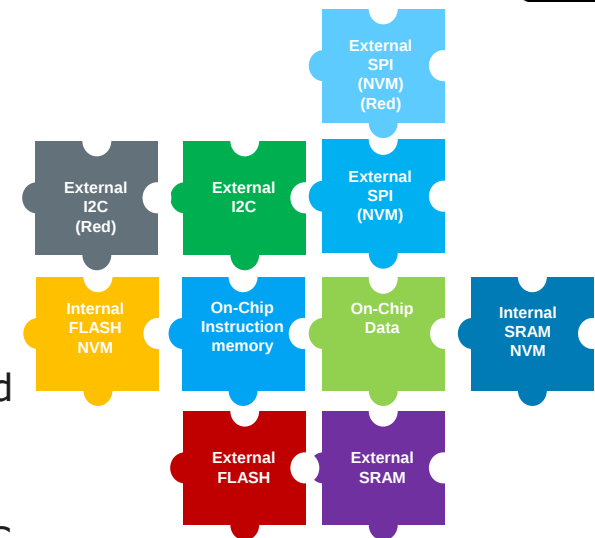
Processor core

- Fault-tolerant **SPARC V8 processor** with 31 register windows and support **16-bit instruction** operation (REX)
- Double precision IEEE-754 floating point unit
- Memory protection units with 8 zones and individual access control of peripherals
- Advanced on-chip debug support unit with trace buffers and statistics
- **Deterministic software execution** and non-intrusive debugging
- **Fast context switching** (PWRPSR, AWP, register partitioning, SVT, MVT)
- **Interrupt zero jitter delay**



Memory support

- **192KiB** EDAC protected **tightly coupled memory** with single cycle access from processor and **ATOMIC** bit operations
- Dedicated SPI Memory interface with boot ROM capability and EDAC
- I2C memory interface with boot ROM capability
- 8-bit SRAM/ROM I/F with support up to 16MiB ROM and 256MiB SRAM
- Scrubber with programmable scrub rate for all embedded memories and external PROM/SRAM and SPI memories
- Redundant boot memory (PROM/SRAM/SPI/I2C/NVRAM)
- Application software container for checking software integrity using CRC
- Boot from internal SRAM, external PROM/FLASH/SRAM/SPI/I2C memory



Support of many variety of memory types

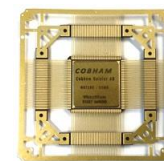
Boot options

- Remote boot (no software or external memory required)
 - UART
 - SpaceWire RMAP
 - SPI / SPI4SPACE
 - I2C
- Internal Boot PROM supported boot (configures the I/Os):
 - External PROM/SRAM
 - External SPI Memory
 - Embedded NVRAM/PROM/SRAM in package (future option)
 - External I2C PROM
- Direct boot (bypass internal boot prom)
 - External PROM/SRAM
 - External SPI Memory
 - Embedded NVRAM/PROM/SRAM in package (future option)

Select Boot option via external pins

Key features – Processor Performance

- On-chip SRAM w/ Dual Port, EADC and Scrubbing, Radiation Tolerant
 - 192 KiB Instruction and Data – User defined mix of instruction vs data
- Integrated Floating Point Unit
 - IEEE-754 compliant floating-point unit, supporting both single and double precision operands
- Memory Protection Unit
 - 8 zones and individual access control of peripherals
- System Clock frequency: 50MHz
 - Dynamic reconfiguration of system clock for low power
- System Benchmark
 - Dhrystone: 1.24 Dhrystone / MHz
 - Whetstone: 0.43 Whetstone / MHz
 - CoreMark: 2.21 CoreMark / MHz
 - EDAC, Scrubbing, DMA transfers and debug are non-intrusive and do not affect performance



Processor	Processor core	LEON3FT
	Architecture	SPARC V8 w. V8e subset
	RISC type	32bit
	Instruction set	SPARC V8(e), LEON REX
	Pipeline stages	7
	Tightly coupled memory	192 KiB
	FPU	IEEE-754
	MPU	yes
	Mul/Div	Mul/Div
	Peripheral DMA	multi-channel
	Interrupt handling	deterministic
	Performance counters	yes
	Debug unit	yes
	Embedded trace buffer	yes
	Processor MHz	50
Performance	Dhrystone / MHz	0.93 / 1.24 / 1.46
	Whetstone / MHz	0.43
	CoreMark / MHz	2.21

* Dhrystone Performance: Compiler Versions and Ground Rules application note is available at <https://www.gaisler.com/index.php/information/app-tech-notes>

Key features – real time

Real Time features and enhancements

- Fast context switching (PWRPSR, AWP, Register partitioning, SVT, MVT)
 - Very low interrupt response time can be achieved by switching register window
 - A unique trap handler can be executed in its own register window (Register partitioning)
 - Benefits from register partitioning:
 - Extremely low interrupt latency
 - All local and input registers are preserved
 - Nested interrupts are supported by hardware
- Interrupt zero jitter delay
- Deterministic software execution and non-intrusive debugging
 - Advanced on-chip debug support unit with trace buffers and statistic unit

□ Custom flat register window model

□ Typical flat register window model (MVT) using BCC 2.0.2

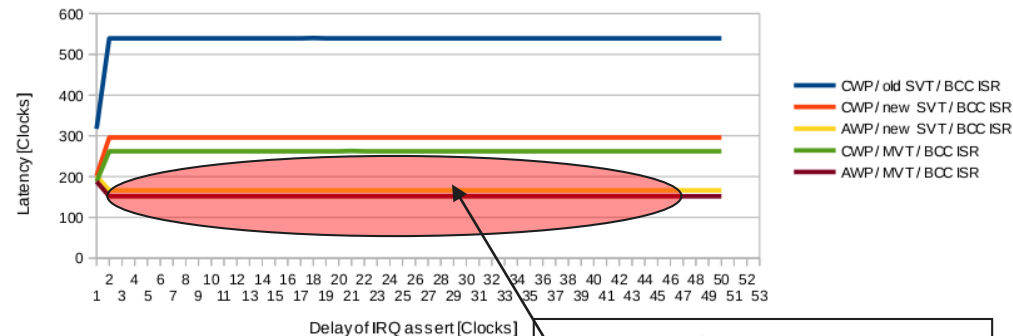
□ Typical flat register window model (SVT) using BCC 2.0.2

	Typical		Worst	
	IRQ to ISR	ISR EXIT	IRQ to ISR	ISR EXIT
BCC 2.0 Custom ISR	11	6	11	6
BCC 2.0 flat ISR	22	15	37	15

Key features – real time

Real Time features and enhancements

- **Fast context switching** (PWRPSR, AWP, Register partitioning, interrupt mapping, SVT, MVT)
- Interrupt zero jitter delay
- Advanced on-chip debug support unit with trace buffers and statistic unit
- **Deterministic software execution and non-intrusive debugging**
- Interrupt Service Routine (ISR) is a user function
 - Normal C function
 - Nesting and chaining with libbcc
- **Fast interrupt**
 - SPARC assembly
 - CPU register limitations
- Measurements on LEON3 GR716:
 - Unit: #cycles.
 - (cycles have to be added) for long instructions (FPU, DIV, etc) being executed at interrupt event.



- Improved system responsiveness
- Improved determinism

	Typical		Worst	
	IRQ to ISR	ISR EXIT	IRQ to ISR	ISR EXIT
BCC 1.0 ISR	196	139	322	-
BCC 2.0 ISR	100	73	200	146

Key features – real time – even faster response is possible

Flat register Model

- Very low interrupt response time can be achieved by switching register window (Flat Register Window)
- Each unique trap handler is to executed in its own register window
- Benefits from flat register window:
 - Extremely low interrupt latency
 - All local and input registers are preserved
 - Nested interrupt are supported by hardware
- Examples is provided with Software environment version 2.0.2 and later

□ Custom flat register window model

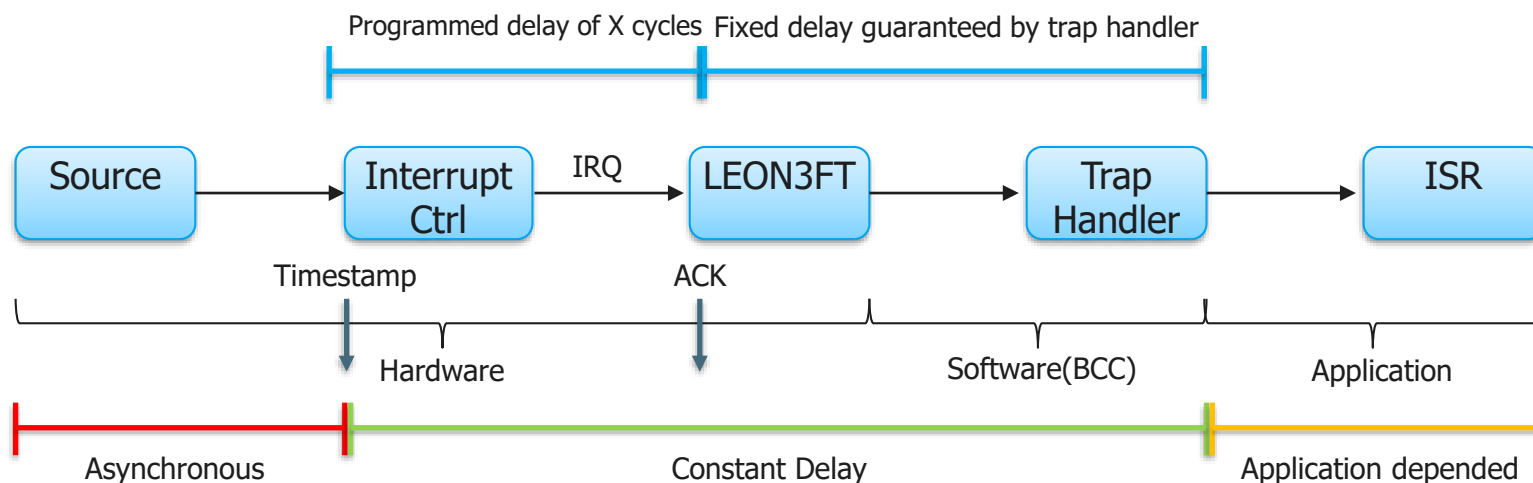
□ Typical flat register window model (MVT) using BCC 2.0.2

□ Typical flat register window model (SVT) using BCC 2.0.2

	Typical		Worst	
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BCC 1.0 ISR	196	139	322	-
BCC 2.0 ISR	100	73	200	146
BCC 2.0 Custom ISR	11	6	11	6
BCC 2.0 flat ISR	22	15	37	15

Key features - constant interrupt delay

- Support for applications requiring constant interrupt delay
- Programmable delay in processor from interrupt assertion -> start of trap handler.
 - Ongoing instruction will finish but 'jump' instruction to trap handler will be held for time set by user. (worst case is floating point instructions)
- Timestamp of interrupts and local counter in processor
 - Access to counter in processor and single cycle access to local instruction memory guarantees no extra delay or jitter
- Possible to set fix delay for trap handler to increase system determinism
- Make use of all 31 available register windows not to get window overflow or overflow



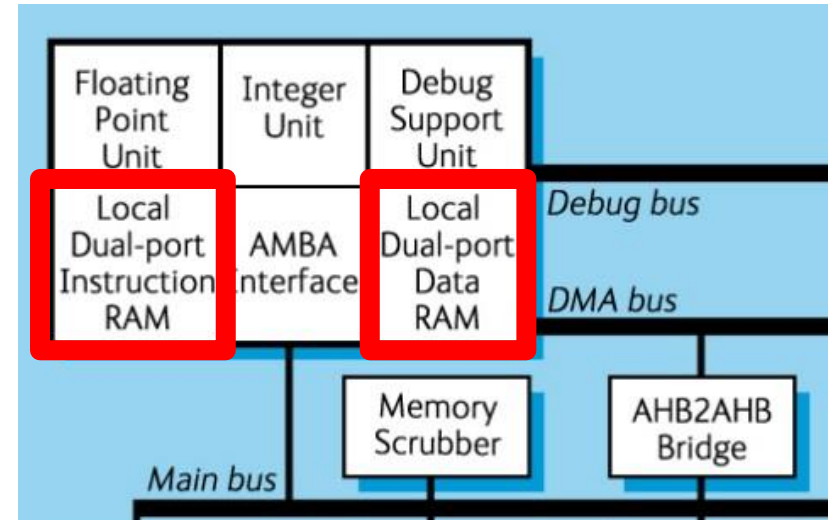
GR716 – LEON3FT Microcontroller

Key features – tightly coupled local memory

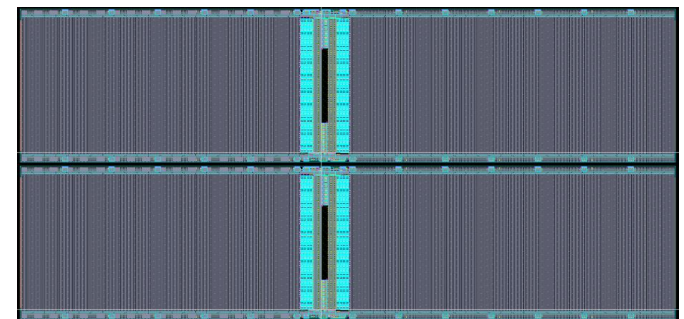
The microcontroller has **local instruction** and **data** on-chip RAM connected to the LEON3FT processor

Local RAM features:

- 128KiB Instruction memory
 - single cycle access
- 64KiB Data memory protected by EDAC
 - single cycle access
- Scrubber support
- Dual port access enables
 - seamless uploading of new program
 - DMA traffic direct into data memory without affecting program execution or data fetch
 - scrubber access and EDAC correction without affecting program execution or data fetch
- Support atomic bit-filed operations
 - OR, AND, XOR, Set & Clear
- Instructions can be executed from data memory and data can be stored in instruction memory



Local instruction and data memory is located close to LEON3FT processor for single cycle access

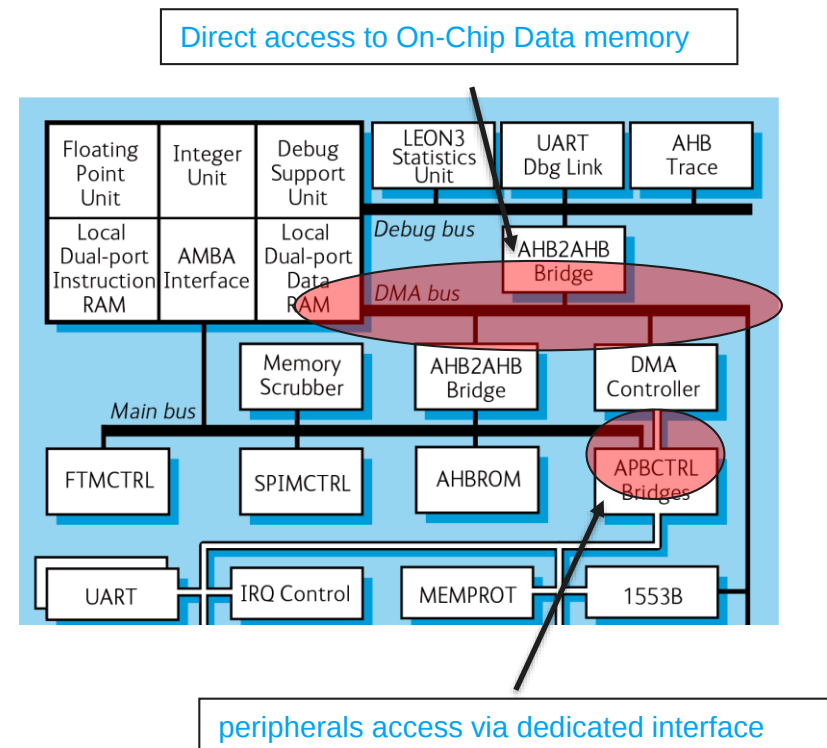


Rad Hardened High density SRAM Integration - Integrated error detection and correction. One error can be corrected and two errors can be detected, which is performed by using a (32, 7) BCH code

GR716 – LEON3FT Microcontroller

Key features - Direct Memory Access Controller

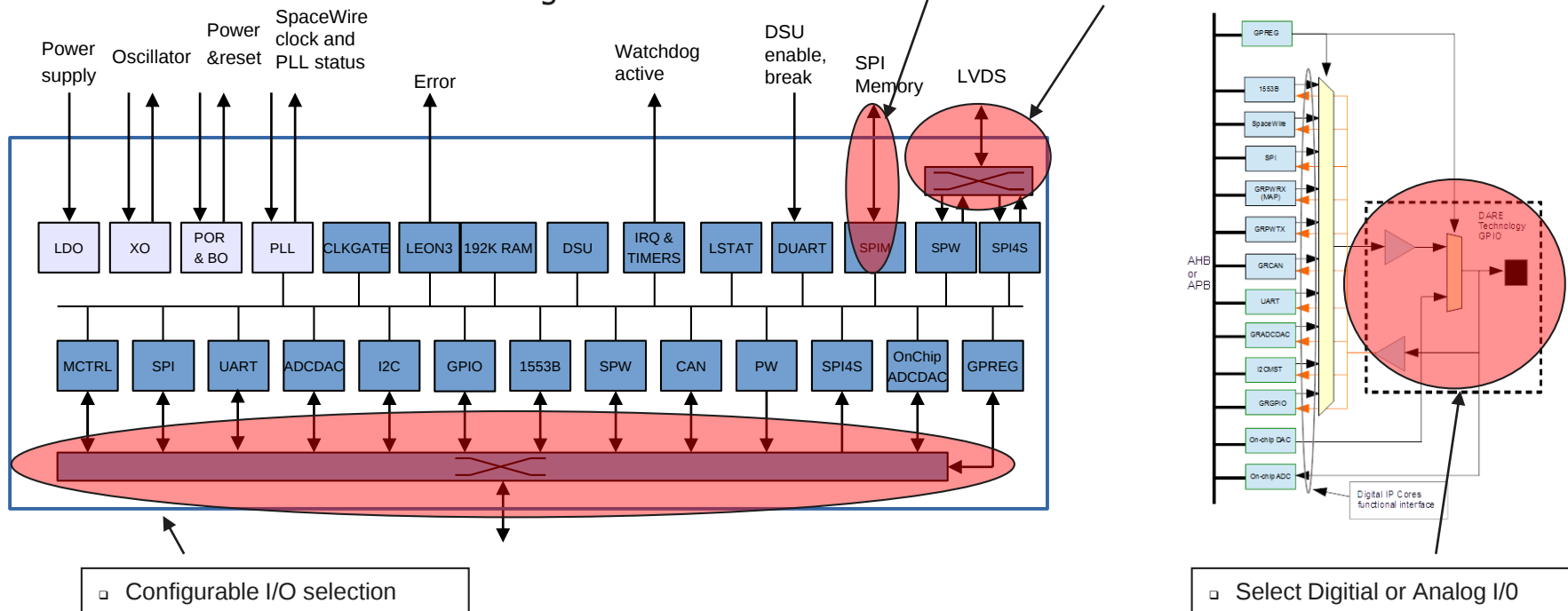
- System DMA overview
 - 4 individual DMA cores (each core has multiple channels)
 - Multiple AHB interface and direct access to APB Peripheral
- Programmable DMA transfers through stand-alone DMA controller
 - Responds to Interrupts, Polling register, Loop support
 - Responds to combination of interrupt and register polling
- Programmable DMA user scenarios
 - Offload processor
 - Autonomous transfers from/to ADC/DAC without CPU intervention
 - Autonomous transfers between: UART to UART, SPI to SPI or I2C to I2C
 - Transfer data, update register synchronous to event e.g. PWM output levels



Key features – inputs/outputs

I/O

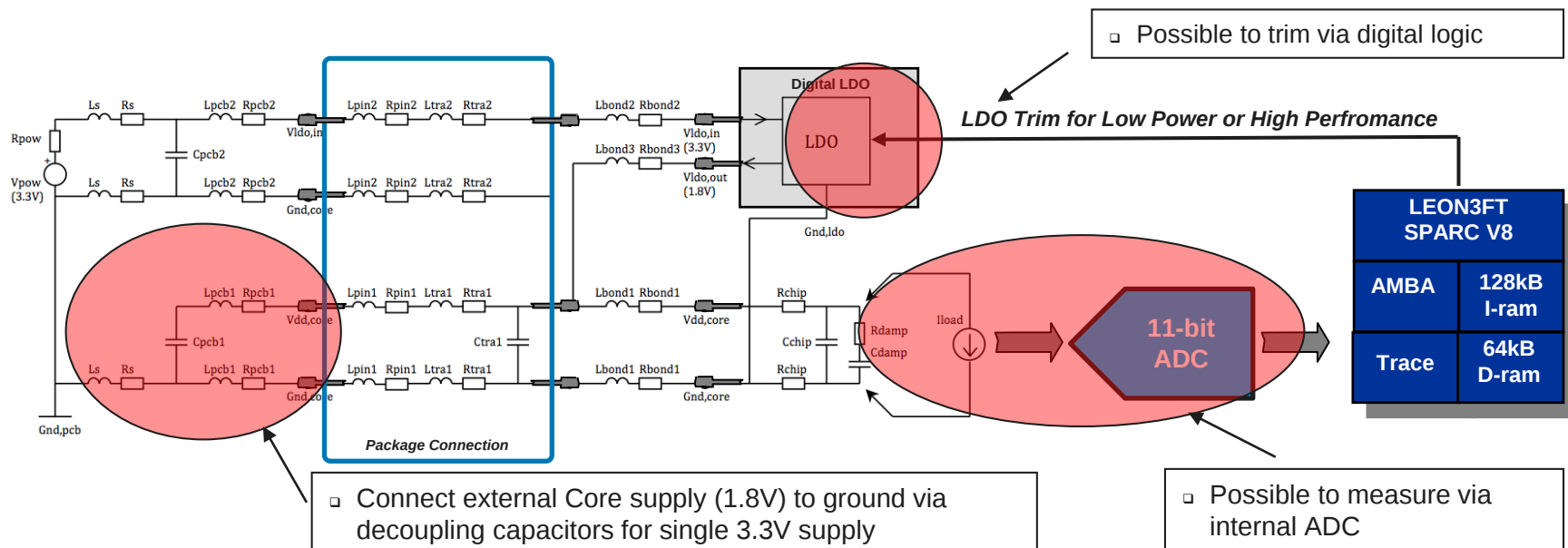
- Configurable I/O selection matrix with mixed signals, internal pull-up/pull-down resistors
- LVDS transceivers for SpaceWire or SPI4Space
- Clock and reset for companion chips e.g. GPIO-expander, external RAM etc.
- Dedicated SPI boot ROM for configuration
- Dedicated Debug Interface
- External Brown Out detection signal



GR716 – LEON3FT Microcontroller

Key features – single supply

- Single $3.3\text{V} \pm 0.3\text{V}$ supply or separate Core Voltage $1.8\text{V} \pm 0.18\text{V}$, I/O voltage $3.3\text{V} \pm 0.3\text{V}$
 - Brown-Out detection for all supplies (sense in package)
 - On-chip Linear regulators with possibility to trim core voltage for lowest power consumption
 - Core Voltage sense via internal ADC.
- Monitoring of core voltage for detecting aging
 - Core temperature can be measured simultaneously



GR716 – LEON3FT Microcontroller

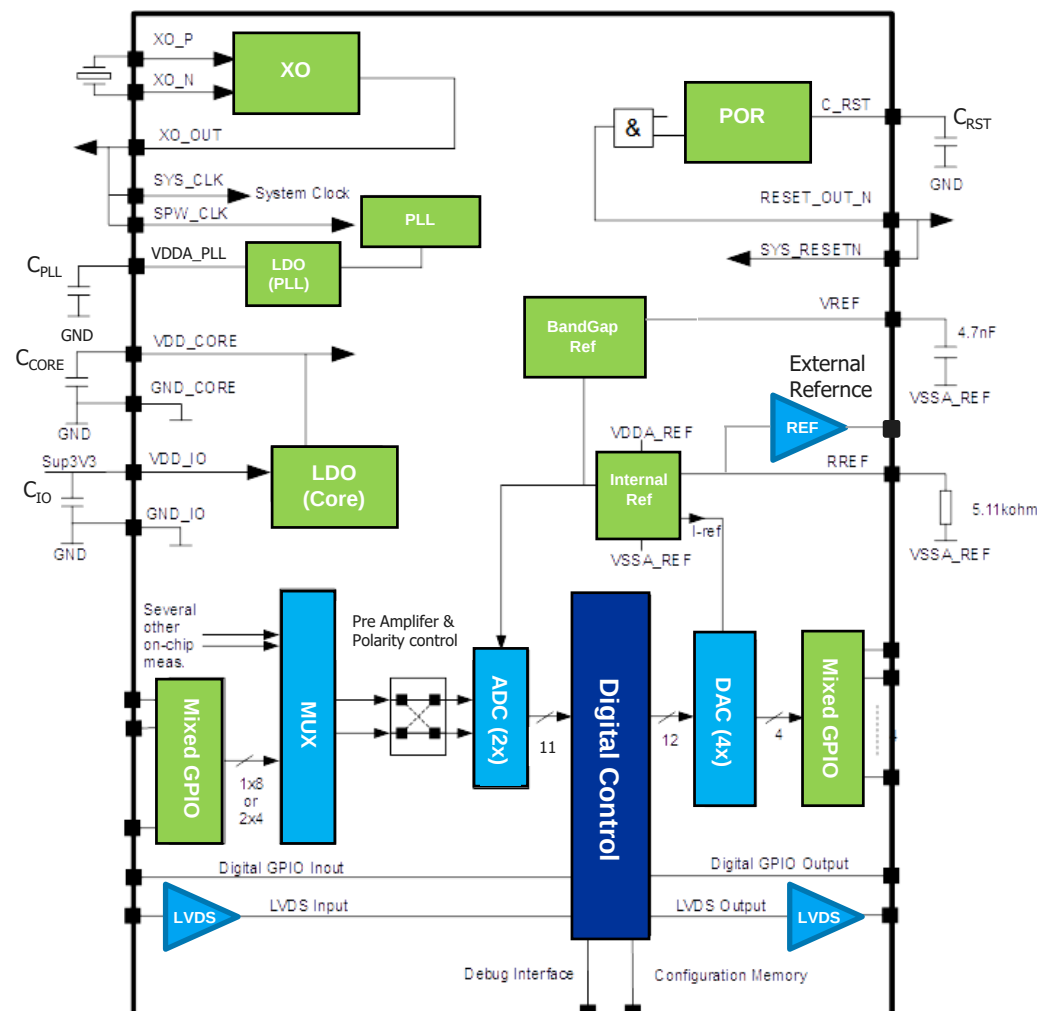
Key features – a minimum of external parts

- Minimum application requirements:

- 3.3V supply
- frequency resonator in the range of 5MHz to 25MHz
- de-coupling capacitor
- reference resistor

- Minimum application enables

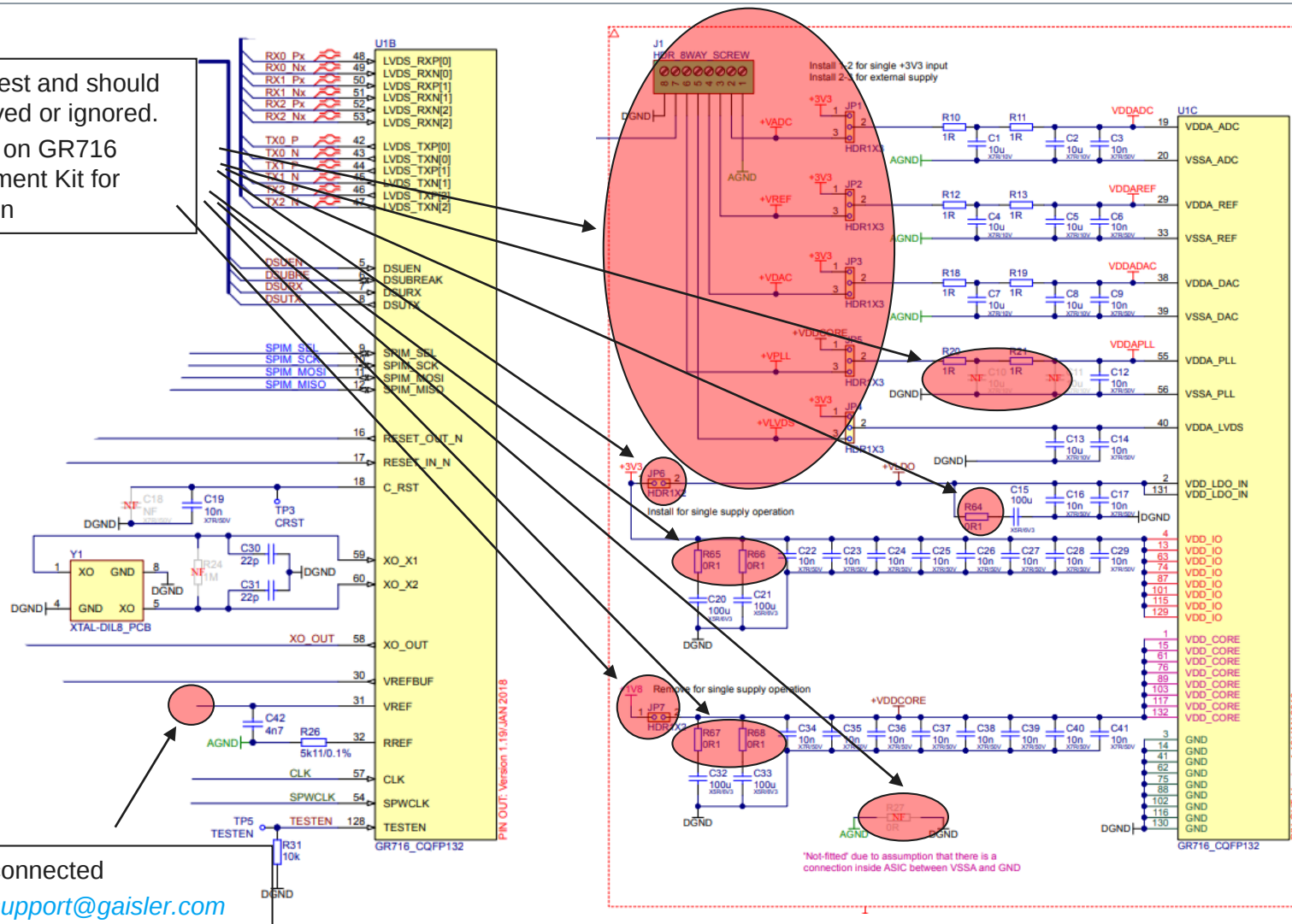
- system clock and reset
- remote access to GR716 via SpaceWire, SPI, UART and I2C
- access to all functions



GR716 – LEON3FT Microcontroller

Key features – a minimum of external parts – In practice...

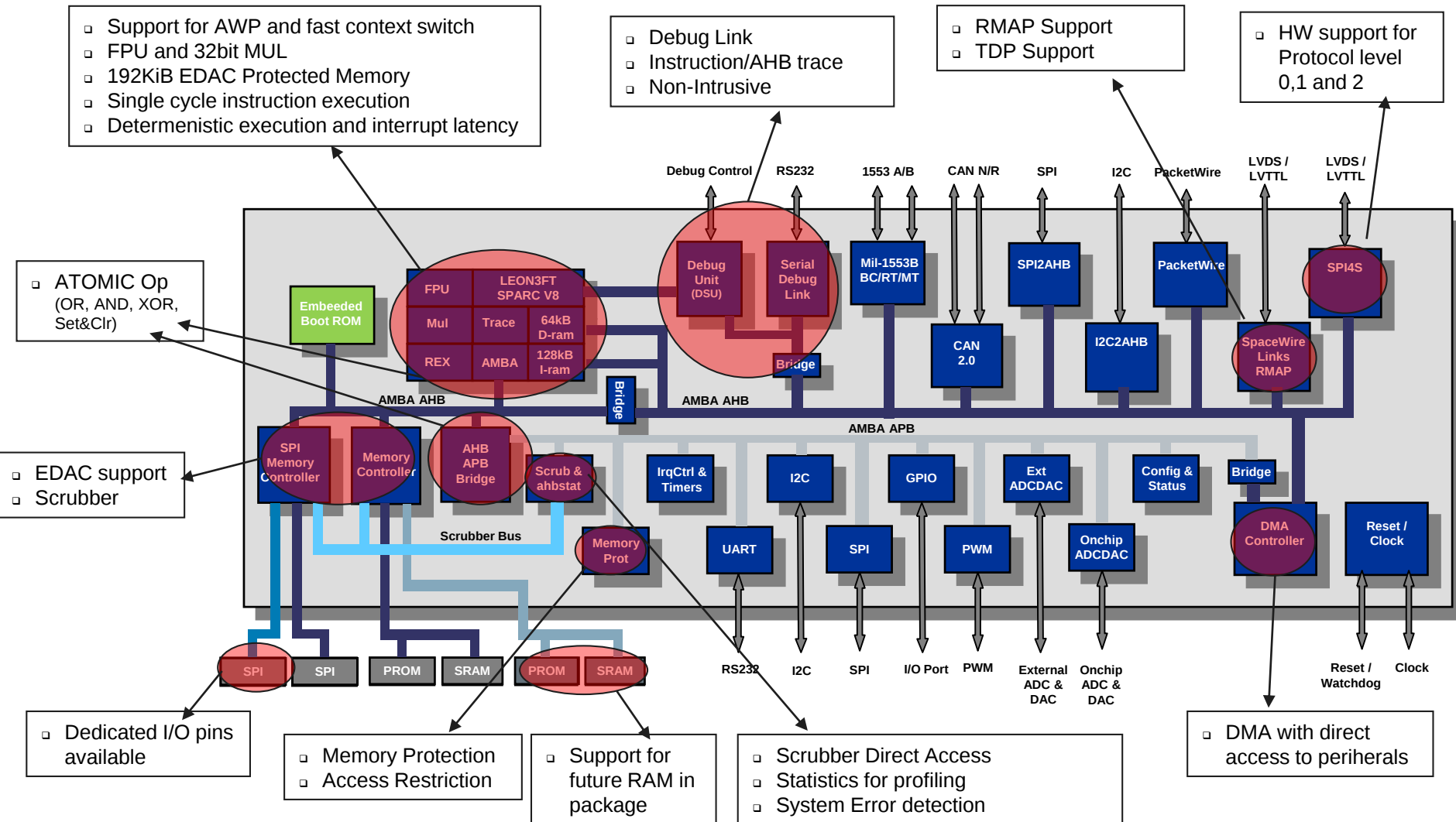
- Internal test and should be removed or ignored.
- Available on GR716 Development Kit for evaluation



- Keep unconnected
- Contact support@gaisler.com

GR716 – LEON3FT Microcontroller

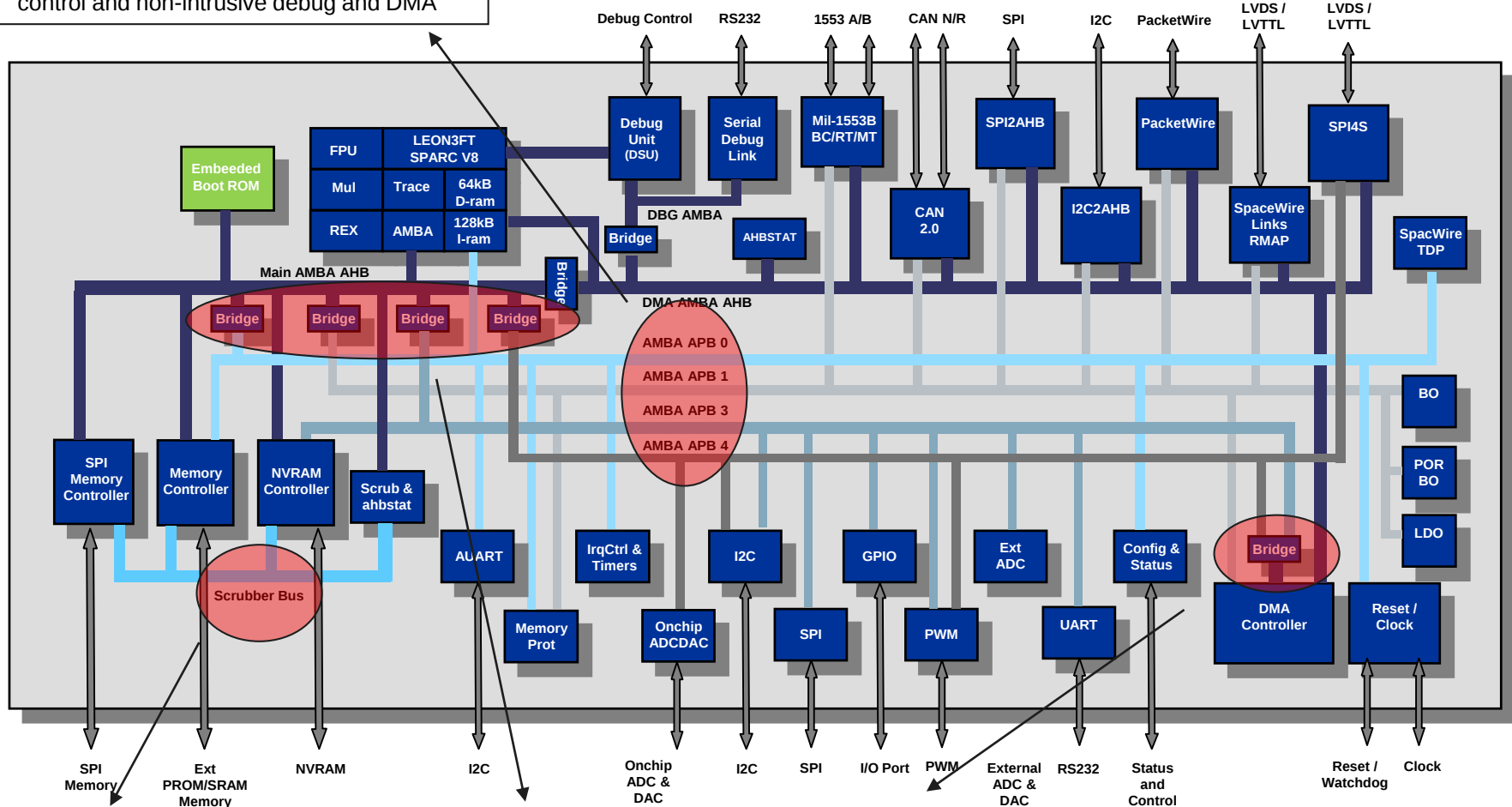
Digital architecture – plenty is not enough



GR716 – LEON3FT Microcontroller

Digital architecture – bus structure

- Multiple APB busses for master access control and non-intrusive debug and DMA

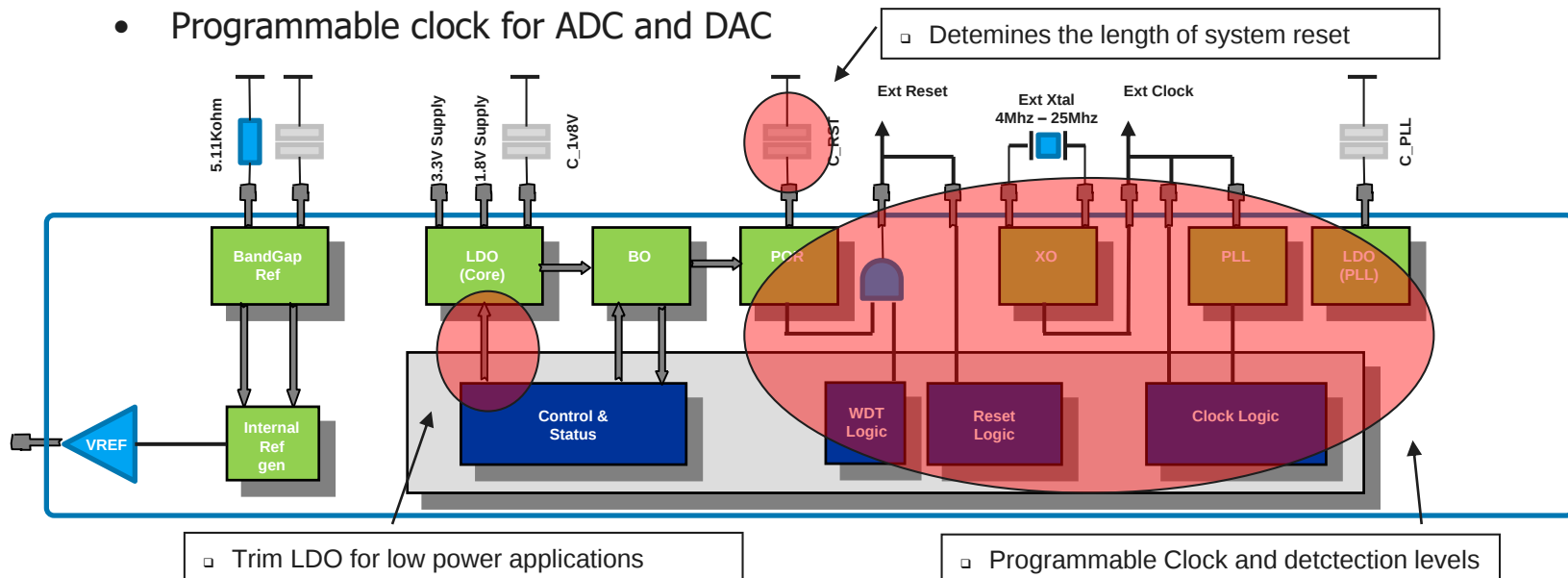


- Scrubber do not affect master bus

- Access control build-in to APB controller

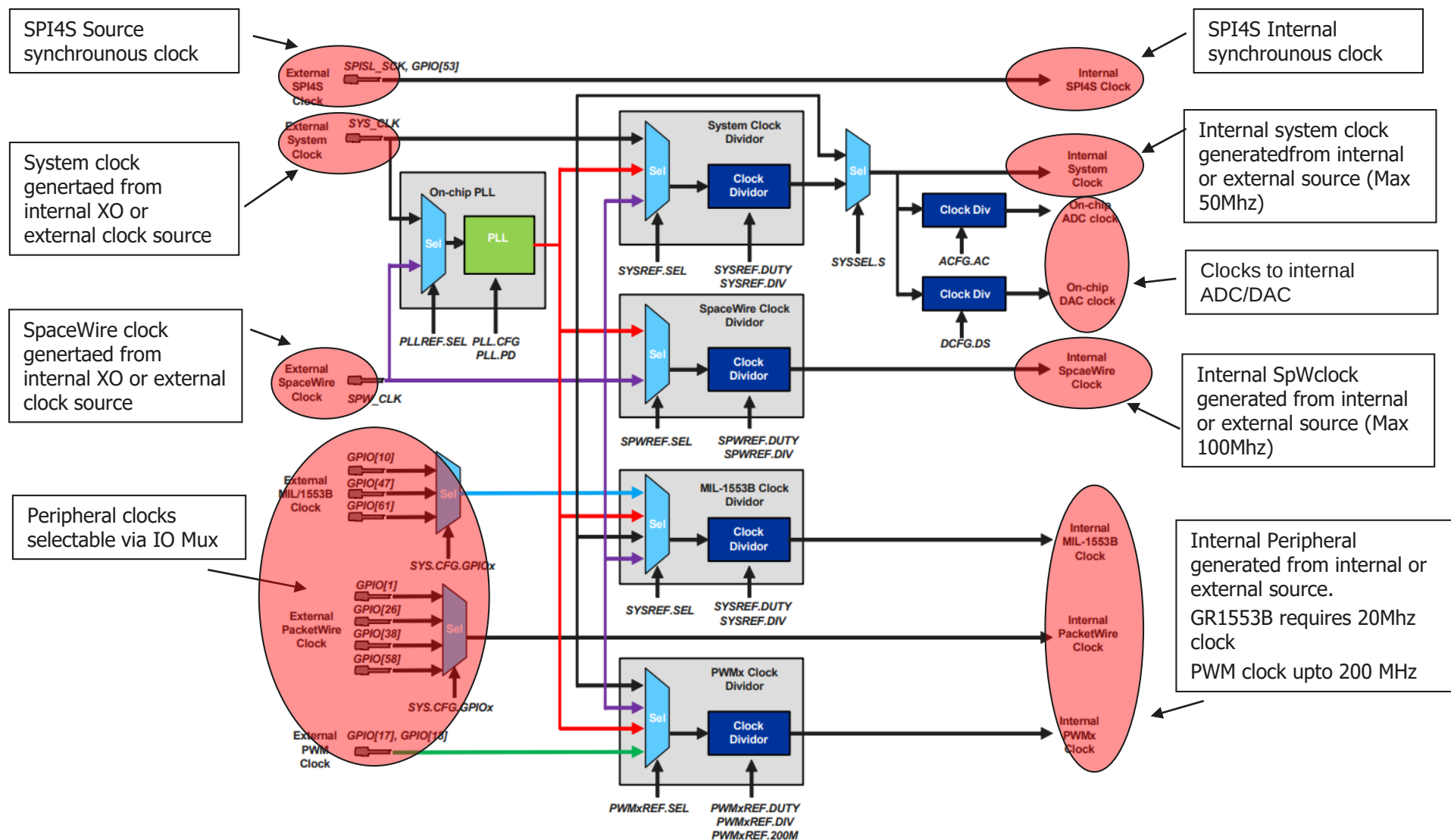
Reset and Clocking Scheme

- Integrated XO, PLL, Power On Reset(POR) and Brown-Out(BO)
 - External system clock and reset
 - Crystal Oscillator support for frequencies from 4Mhz to 25Mhz
 - Programmable Rad-Hard PLL for generation of system and SpaceWire clock
 - Brown out detection on all major power domains (IO, Core, ADC, DAC, REF and PLL)
- Programmable Peripherals clocks
 - Select internal generated clock or external clock for flexibility
 - Programmable clock for ADC and DAC



GR716 – LEON3FT Microcontroller

Reset and Clocking Scheme – Internal Clock Generation



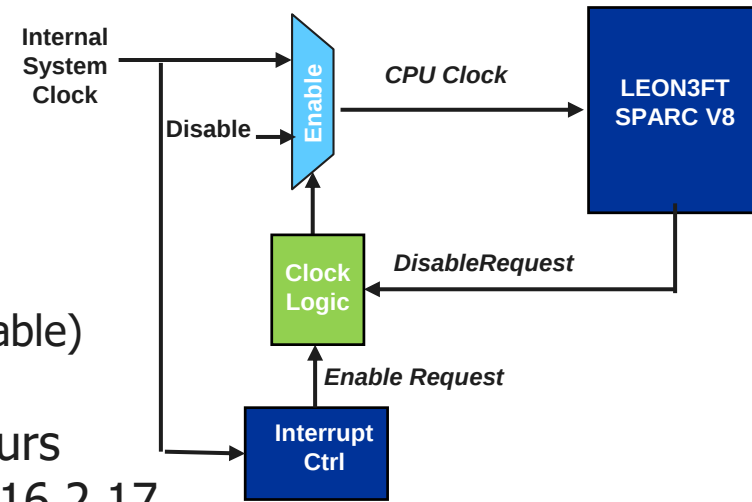
Reset and Clocking Scheme – Internal Clock gate and reset

- Processor Idle state (Deep Sleep)
 - Processor and Memories can enter idle state at any time

```
// Call Idle state from Software  
bcc_power_down();
```

```
// .. Or Request power down mode  
wr %g0, %asr19
```

- Processor will wake up on events (programmable)
- Disable processor clock to save power
- Pipeline is halted until next interrupt occurs
- More information see Datasheet section 16.2.17

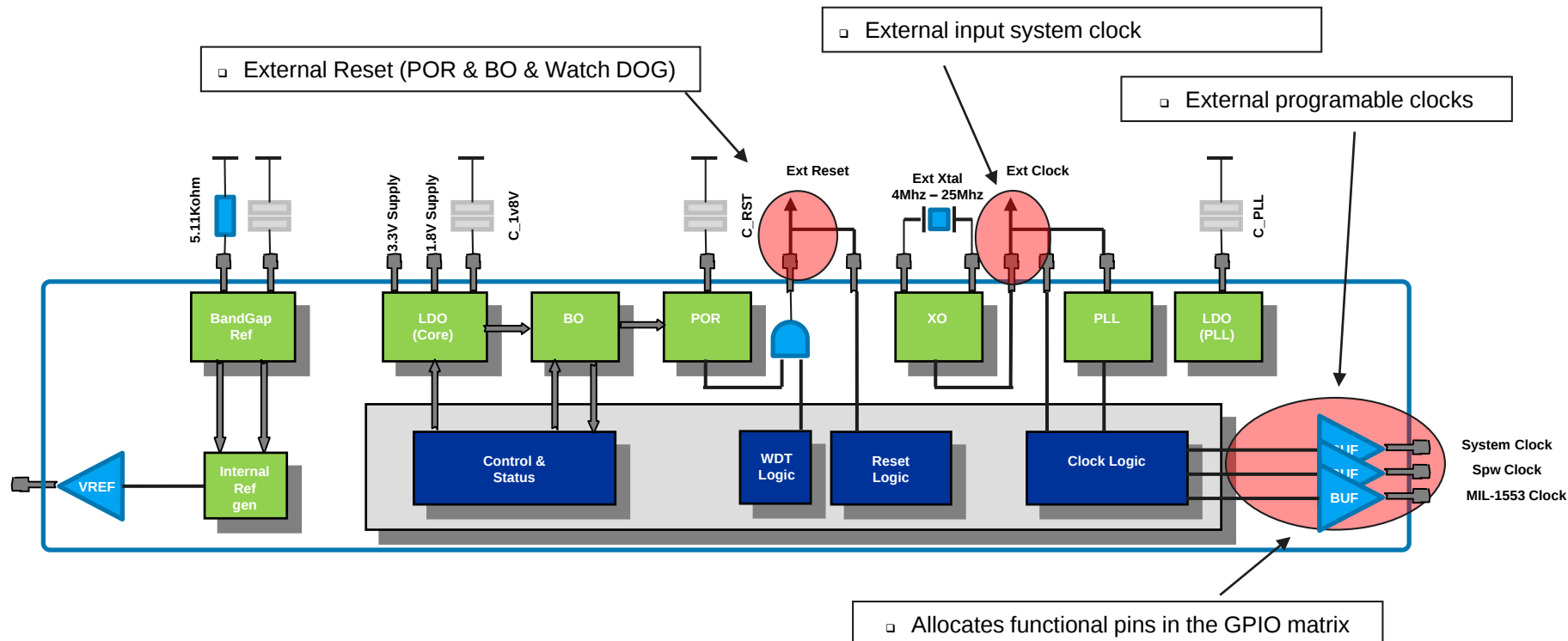


- Peripheral clock and reset control
 - Individual clock and reset control of all peripherals and functions
 - After startup minimum number of peripherals and functions are enabled
- System, SPW, MIL-1553B and PWM clock control
 - Individual control of clocks using internal dividers

GR716 – LEON3FT Microcontroller

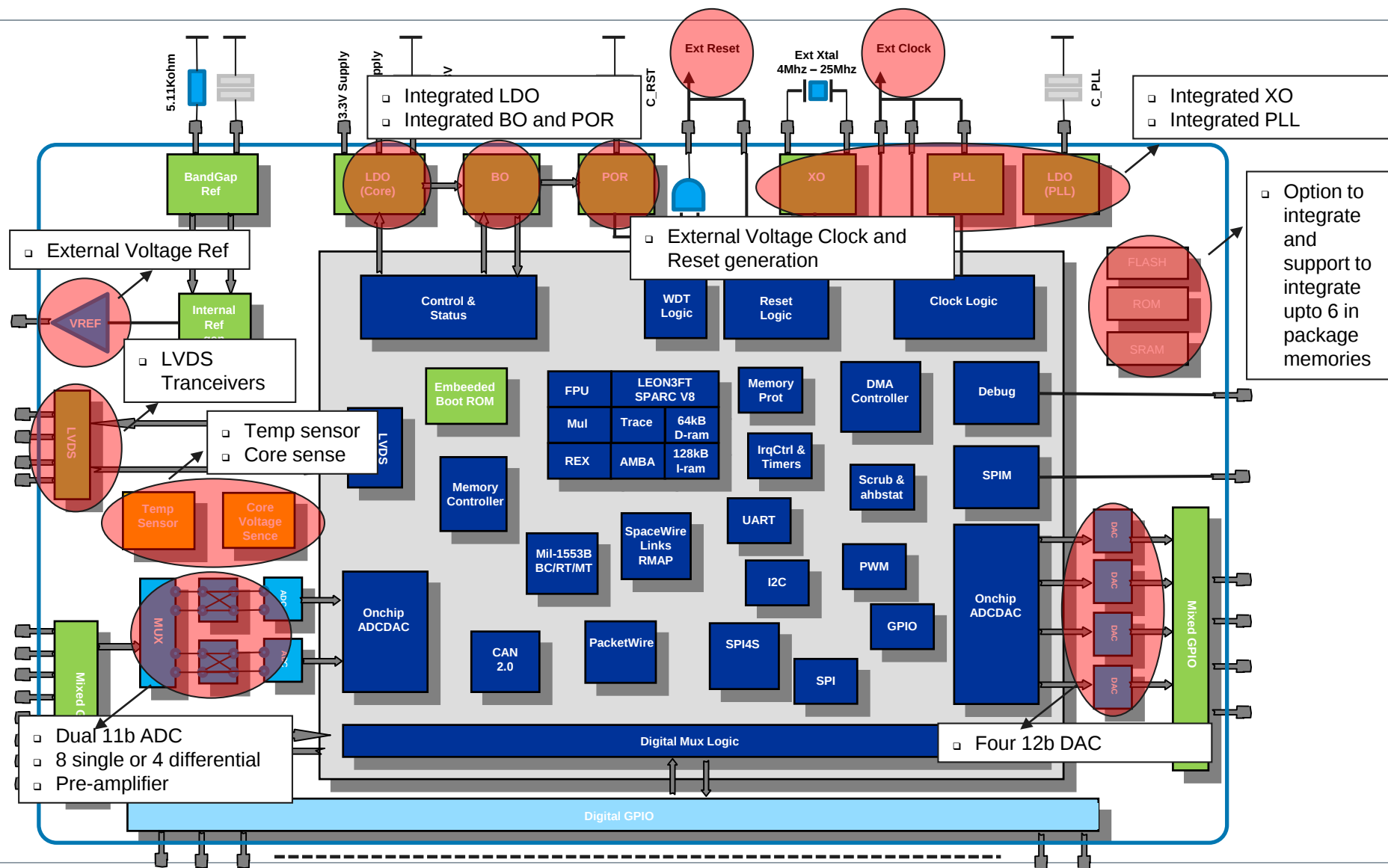
External Reset and Clocking Scheme

- External Reset
 - Power on reset
 - Brown Out detection and Watch Dog
- Internal programmable clocks
 - Possible to output internal generated System, SpaceWire and MIL-1553 clock



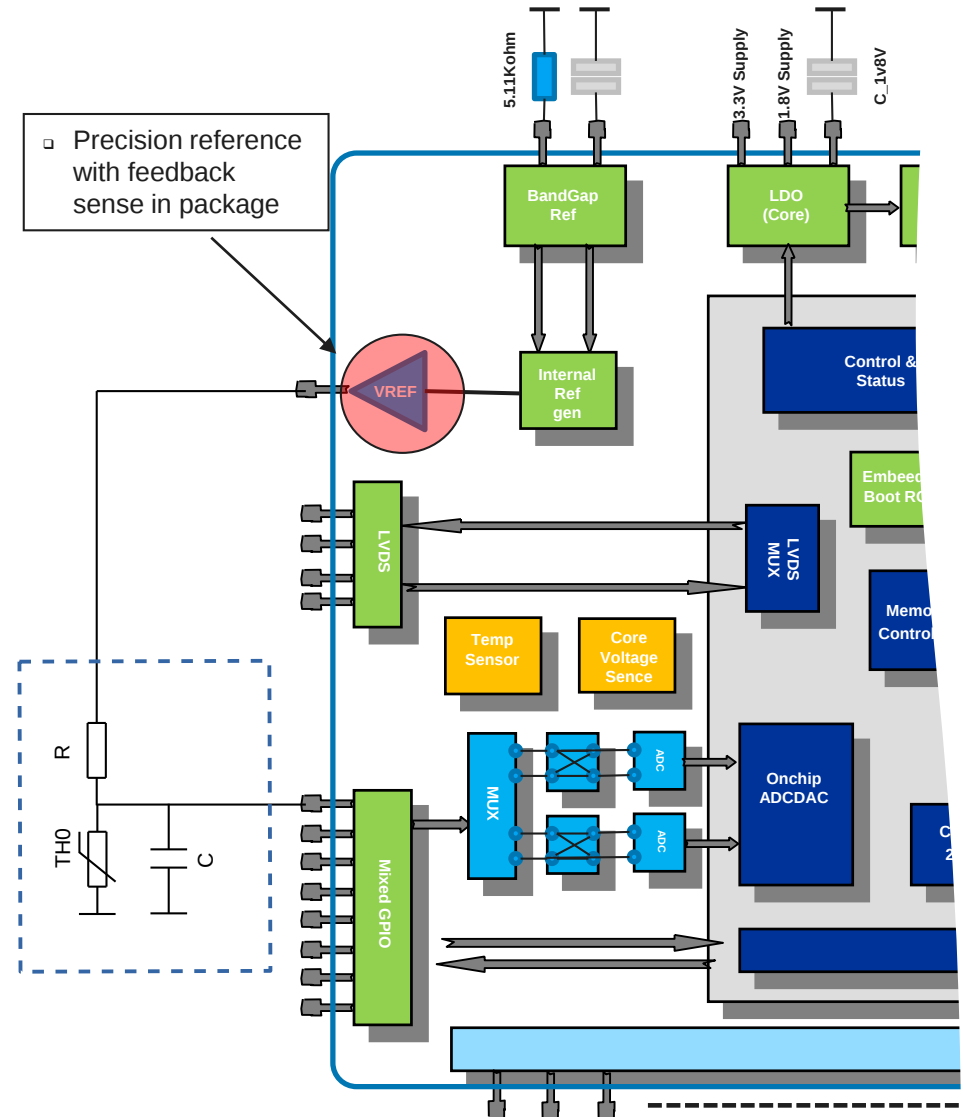
GR716 – LEON3FT Microcontroller

Analogue architecture – Schematic Overview



Analog feature Overview – External precision reference

- Thermistor Measurements Application
- Internal ADC and External Thermistor use the same precision voltage reference
- Internal precision voltage reference can be used as external voltage reference on PCB. (Max 2mA load. Higher load application requires external buffer)
- Sense in package for precision reference

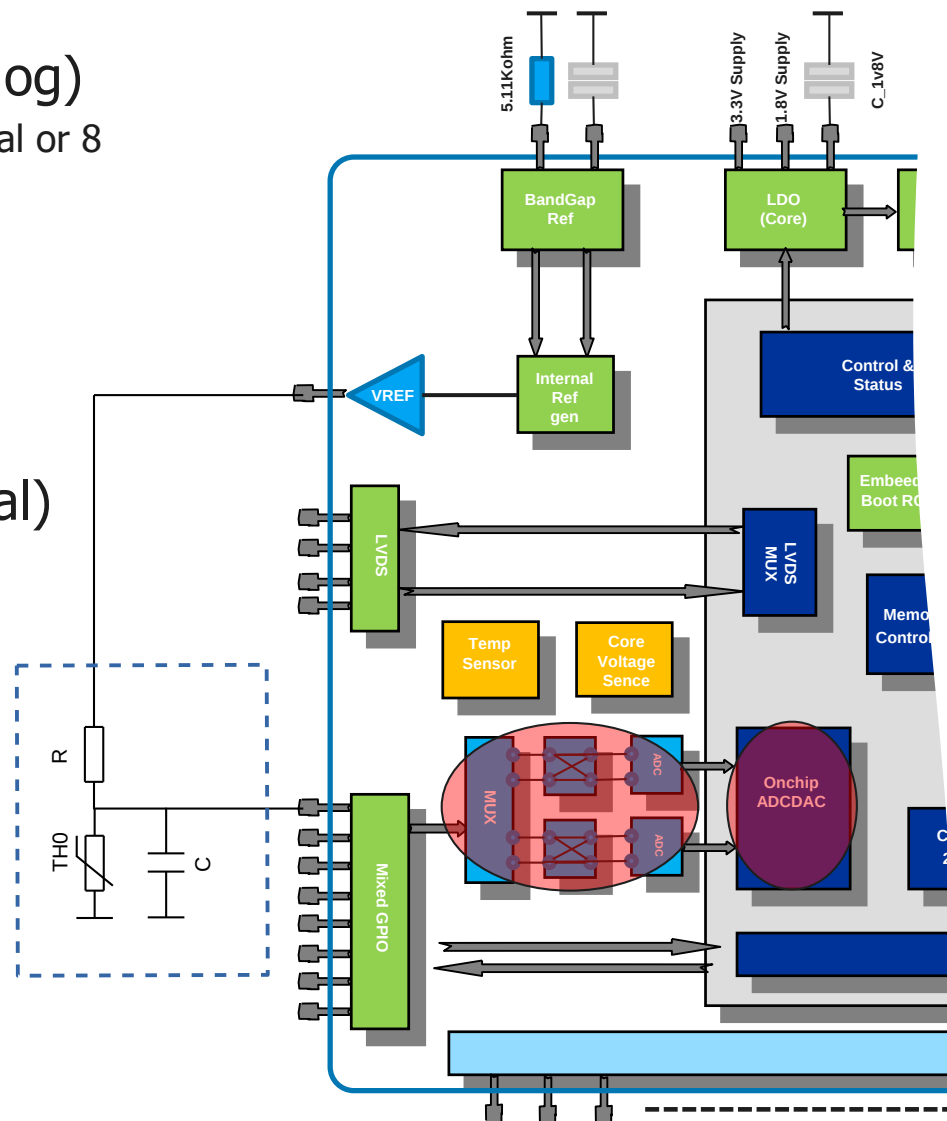


- Analog to Digital Converter (Analog)

- 11bits @ 300Ksps, 4 channel differential or 8 channel single ended (possible to mix)
- Pre-amplifier (0dB, 6dB or 12dB)
- Dual Sample and hold circuits
- Temperature sensor
- Monitor core voltage

- Analog to Digital Converter(Digital)

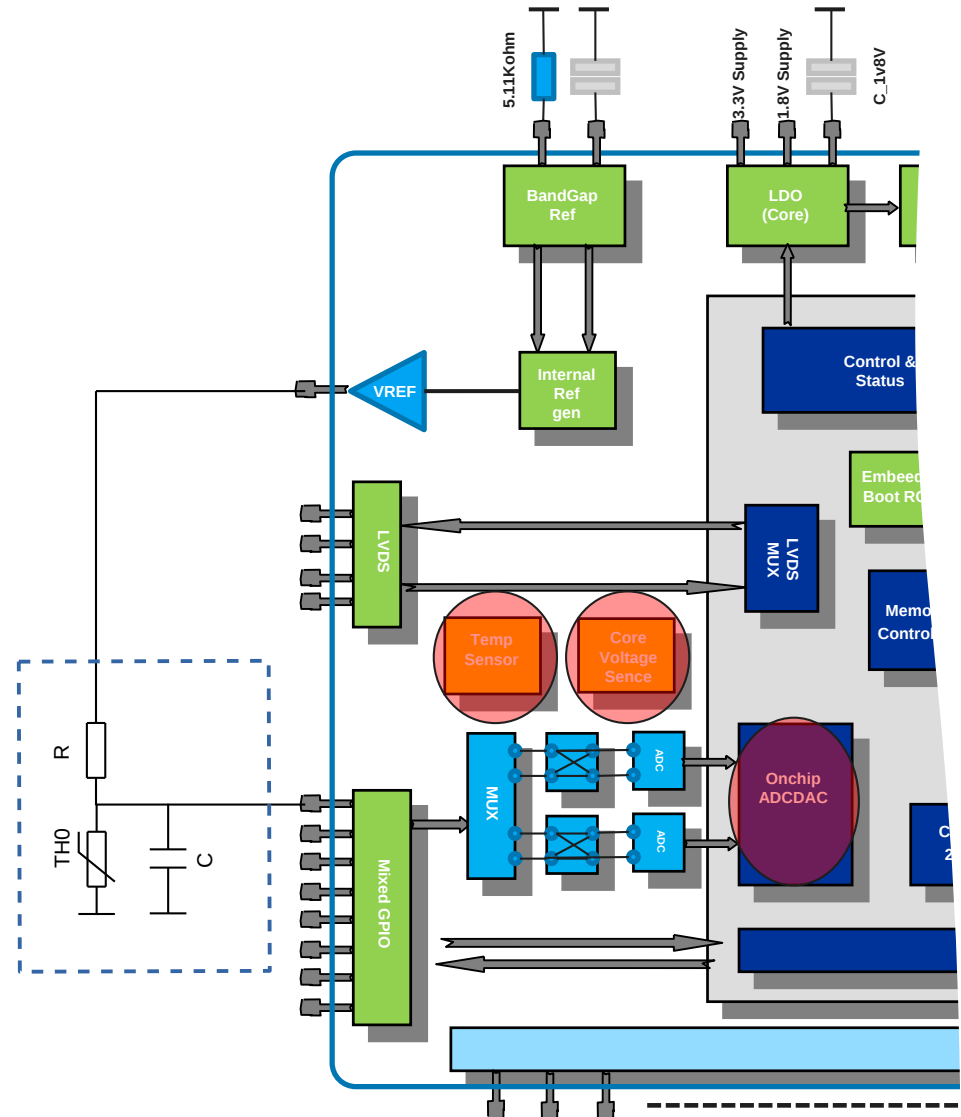
- Oversampling support
- Sequence programming
- Automatic level supervision
- Automatic pre-amplifier control
- Programmable sample triggers. Possible to trigger on internal and external events
- Automatic channel arbitration
- DMA support, automatic transfer of data to local or external RAM
- Low noise sampling support



GR716 – LEON3FT Microcontroller

Temp Sensor and Low Power Mode (Core Voltage)

- Onchip Temperature Sensor
 - Temperature sensor
 - Measured via on chip ADC #0 (connected via separate channel)
- Core Voltage Sense
 - Monitor core voltage
 - Trim Voltage for low of high power applications
 - GR716 always starts up using high power mode
 - Measured via on chip ADC #1 (connected via separate channel)

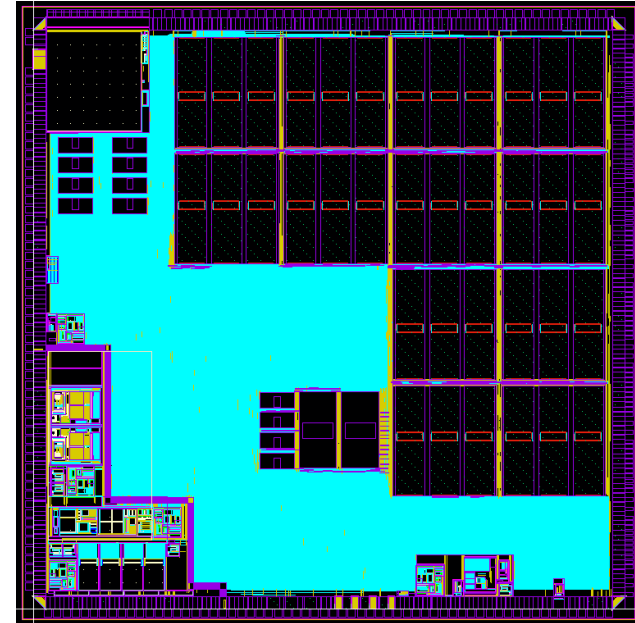


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Key features – Integrated Analogue features

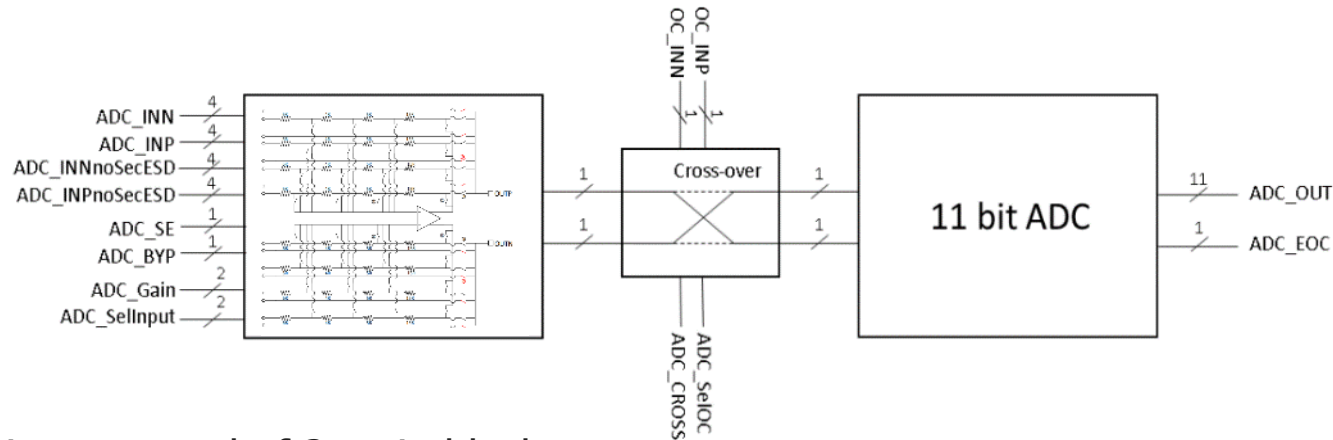
- RadHard 11 bits 300KS/s SAR ADC with Pre-amplifier
- RadHard 12 bit 3.75MS/s DAC
- RadHard Crystal Oscillator
- RadHard Power On Reset
- RadHard 1.8V and 3.3V voltage monitors
- RadHard GPIO with local Power on Control
- RadHard LVDS transceivers with build-in reference
- RadHard voltage and current reference
- RadHard Low-drop regulators
- RadHard external voltage references
- RadHard high density RAM with EDAC protection
- RadHard PLL
- Temperature sensors and core voltage sense



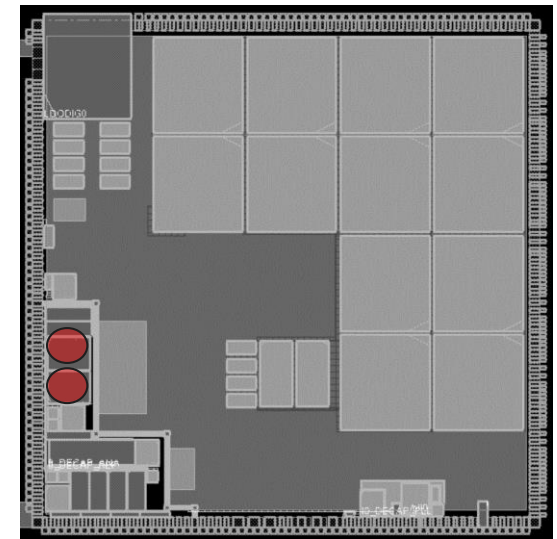
lmec

esa

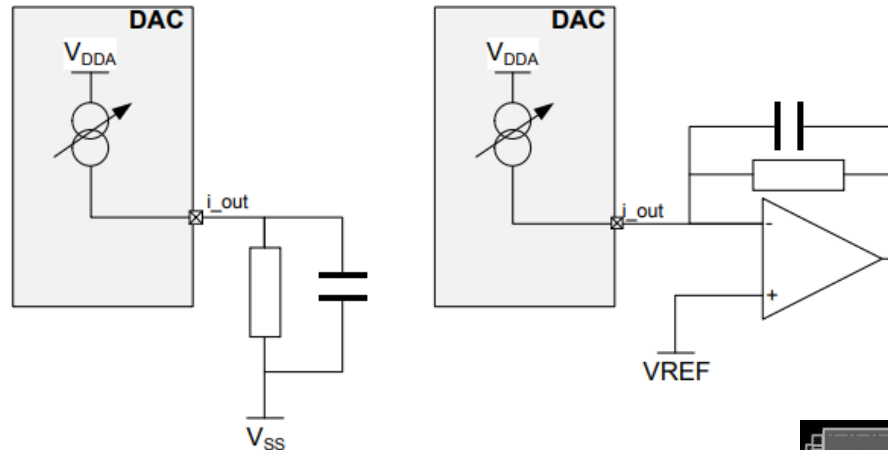
Analogue architecture – Dual 11 bits 300KS/s SAR ADC with Pre-amplifier



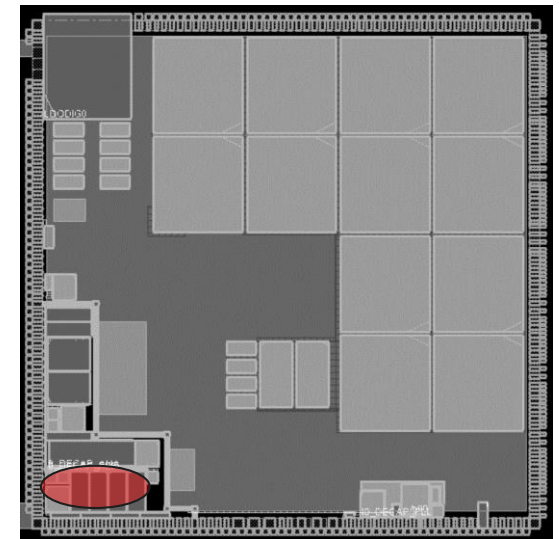
- The ADC is composed of 3 main blocks:
 - An analog mux 8:2 combined with an auto zeroed-amplifier (0dB, 6dB and 12dB)
 - Cross-over block for swapping inputs
 - A differential and single ended SAR ADC (11b, 300kS/s) with internal voltage reference.
- Design is hardened against SET and SEU:
 - Control logic use exclusively rad-hard Flip-Flops (HIT)
 - Data out bits are hardened via Muller-C filter.
 - Clock paths hardened via IMEC DARE180 clock driver cells
 - Analog filters to prevent SET events on configuration inputs



*Dual RadHard 11 bits SAR ADC
Integration*



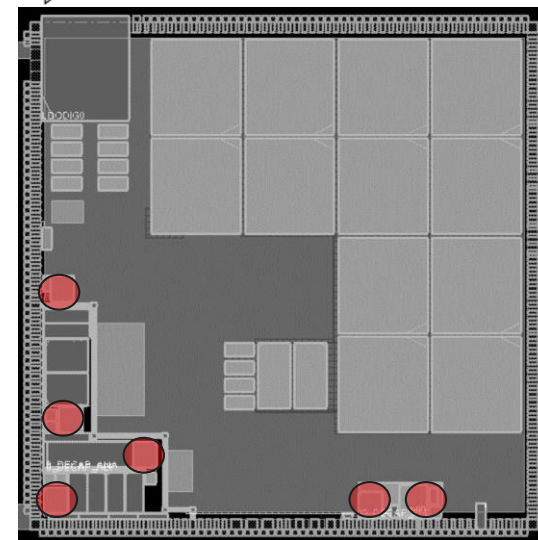
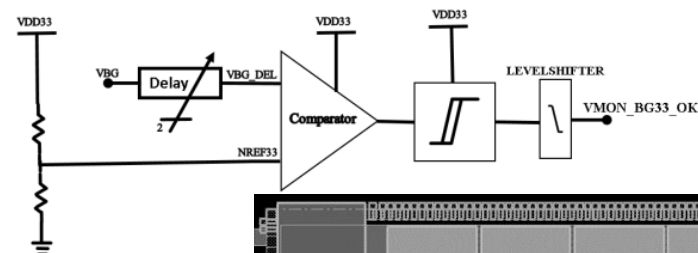
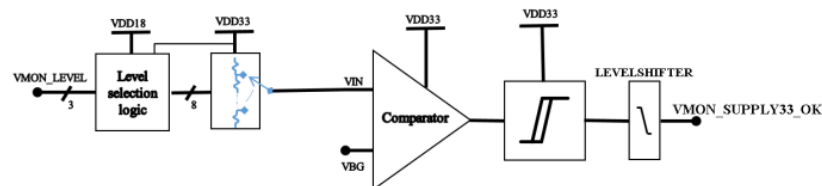
- Four individual current steering DAC with dedicated supply
- Two operation modes available:
 - High accuracy with maximum data rate of 58.6kS/s (DEM mode)
 - Fast mode with maximum sampling data rate of 3.75Ms/s (Non-DEM mode)
- The fast mode and the high precision mode need to use virtual ground



RadHard DAC Integration

Analogue architecture – Voltage monitor

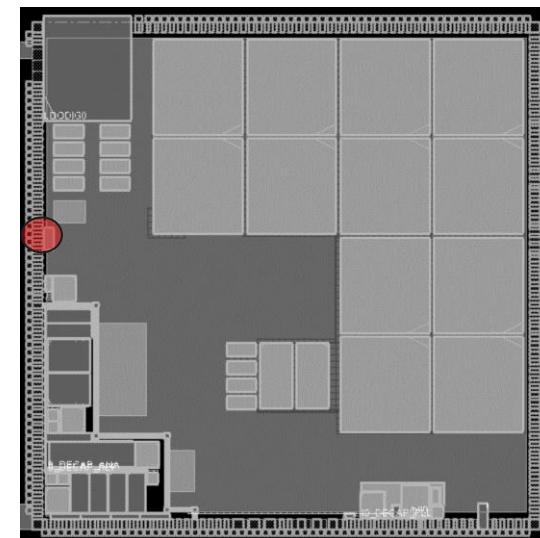
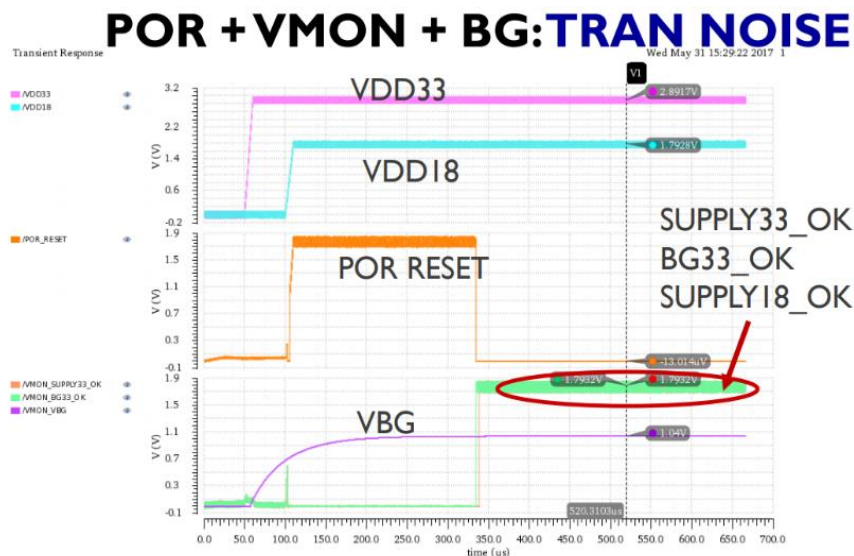
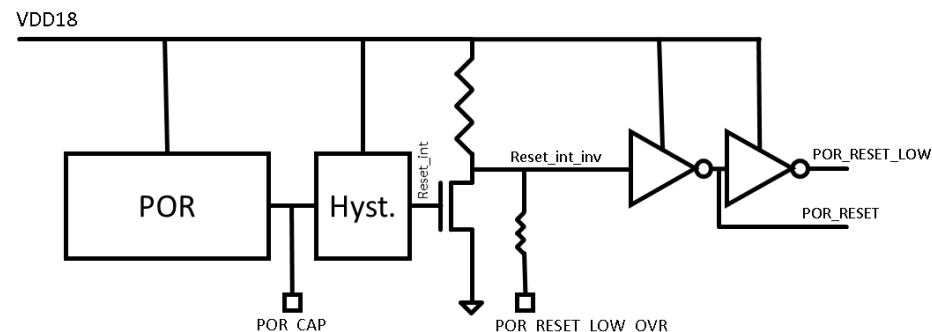
- 1.8V and the 3.3V supplies monitored with internal filtering ($\sim 20\mu\text{s}$).
- 3 bits threshold configuration:
 - From 1.6V till 1.8V.
 - From 2.9V till 3.24V.
- Voltage sense is made in package to detect failure as early as possible.
- Voltage monitor implemented for external and internal voltage supplies.
 - 6 separate voltage monitor for monitoring each separate voltage domain
- Voltage monitor can disable output drivers to avoid malfunction or driver contamination.



Voltage Monitor Integration

Analogue architecture – Power On Reset

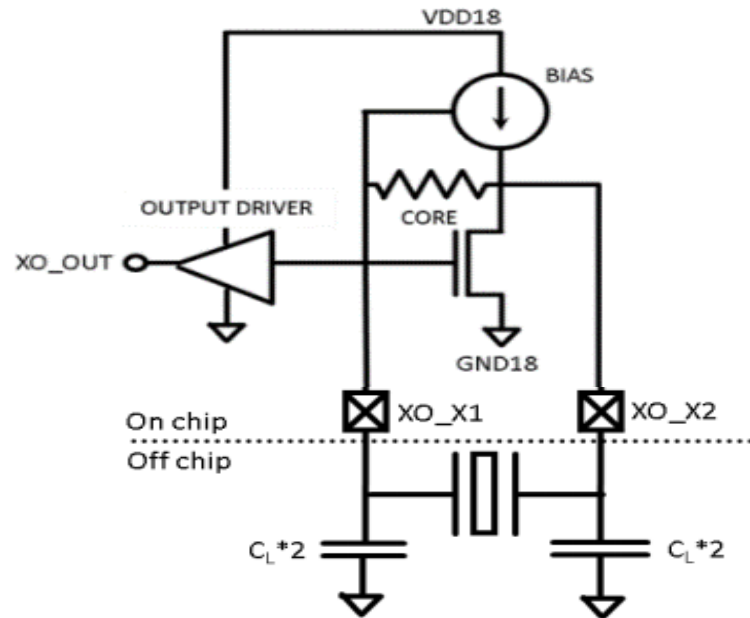
- Programmable reset pulse duration:
 - 235 μ s without external capacitor
 - 150 ms with external capacitor of 220nF
- SET free at 60 MeV*cm²/mg
- External reset is glitch free and can be used as system reset



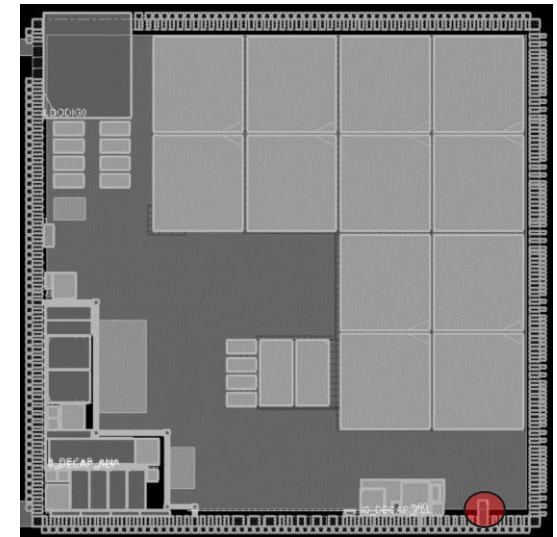
Power On Reset Integration

GR716 – LEON3FT Microcontroller

Analogue architecture – Crystal Oscillator



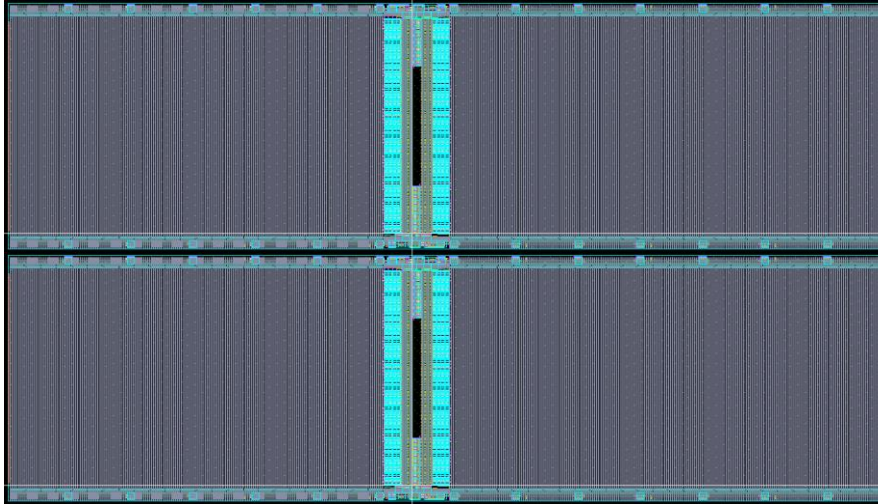
- External clock generated from the crystal is available for the system.
- Support Space Grade and commercial crystals in the range of 5MHz to 25MHz.
- SET hardened:
 - no false edge on the clock can happen
 - maximum period error due to SET of 1.1ns and 3.8ns when respectively running at 25 MHz and 5 MHz (60MeV*cm²/mg)



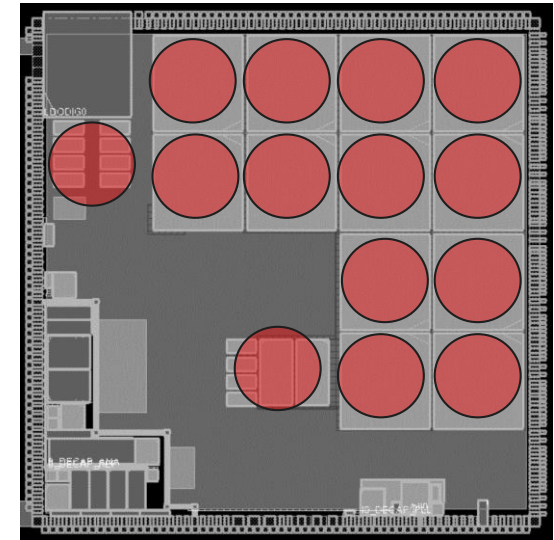
Crystal Oscillator Integration

GR716 – LEON3FT Microcontroller

Analogue architecture – High density SRAM



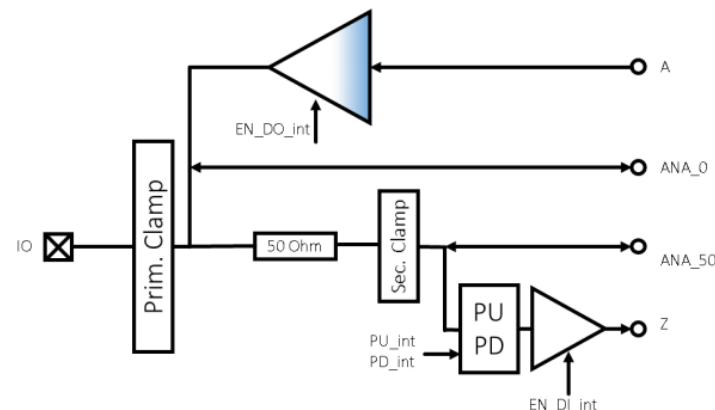
- 192KiB on-chip tightly coupled data and instruction RAM for the processor
- Integrated error detection and correction. One error can be corrected and two errors can be detected, which is performed by using a (32, 7) BCH code
- Programmable Scrubber
- Build-in memory test for device boot report and production test using March C- test algorithm



*RadHard High density SRAM
Integration*

Analogue architecture – GPIO with local Power On Control

- Can be used as:
 - Digital input (Schmitt trigger) with programmable pull up/down
 - Digital output (4mA)
 - Analog input (serial impedance of 50 Ohms)
 - Analog output
- When configured in digital input/output mode the GPIO is completely SET free and use only ELT layout for the NMOS transistors to make it insensitive to radiation effect.
- Its local Power On Control force the IO output in high impedance mode as long as the core voltage is not turned-on. Practically this high impedance mode will be maintained after the ramp-up of the core voltage thanks to the Power On reset



Mixed Analog and Digital GPIO Integration

Typical applications

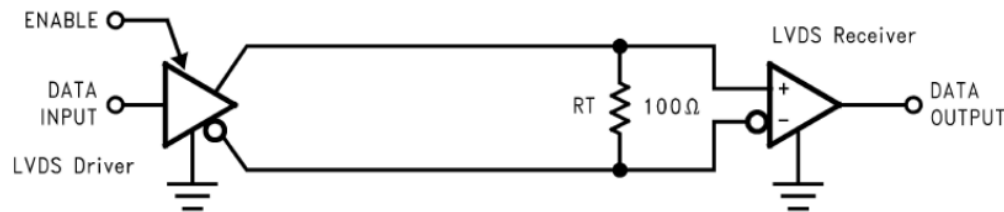
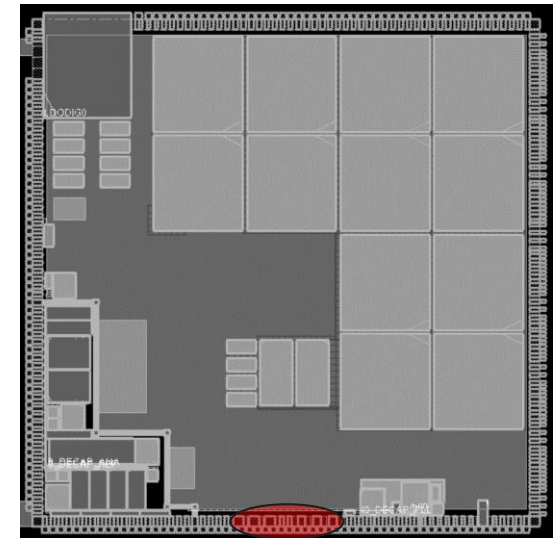


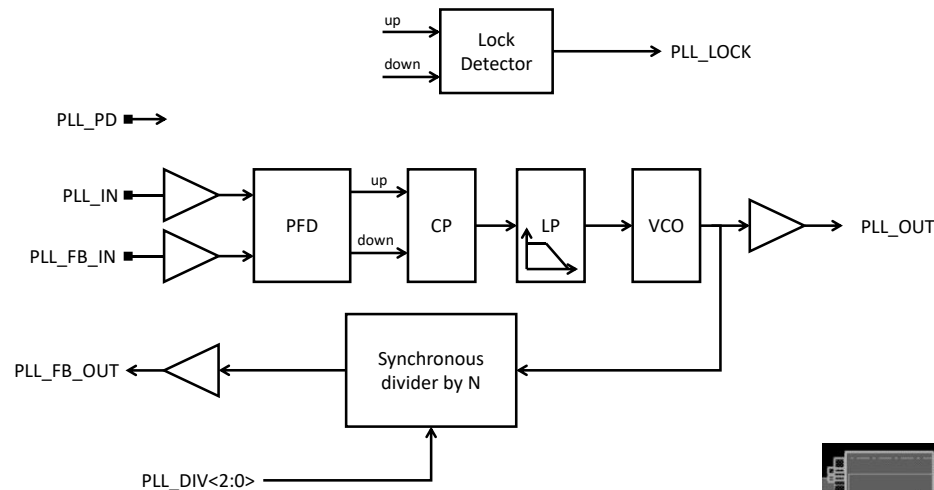
Figure Point-to-point Application

- LVDS driver, transmitter and bias reference are radiation hardened and compliant with the TIA/EIA-644-A standard
- Precision on-board reference for integration and performance
- On-chip LVDS transceivers for SpaceWire and SPI for Space and dedicated pins for external SPI boot ROM are available and can optionally be used

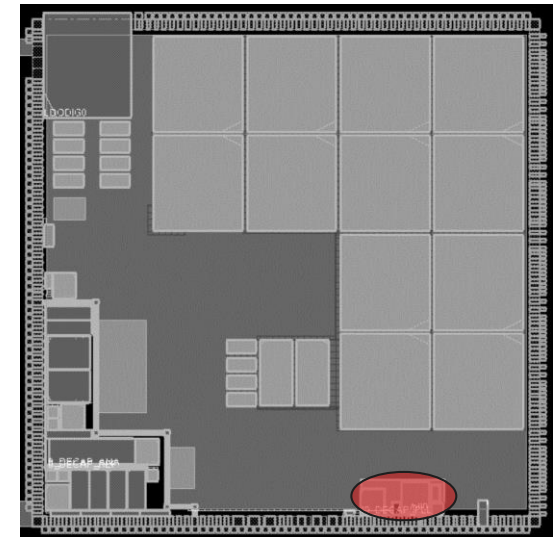


*LVDS with precision reference
Integration*

Analogue architecture – 400 MHz PLL



- Programmable clock divider: 8, 16, 20, 32, 40 and 80
- Low jitter: 600fs in typical condition
- VCO hardened against SET ($60\text{MeV}\cdot\text{cm}^2/\text{mg}$):
 - No false edge
 - Max phase error of 160ps at 400MHz
 - Max phase error of 600ps at 280MHz

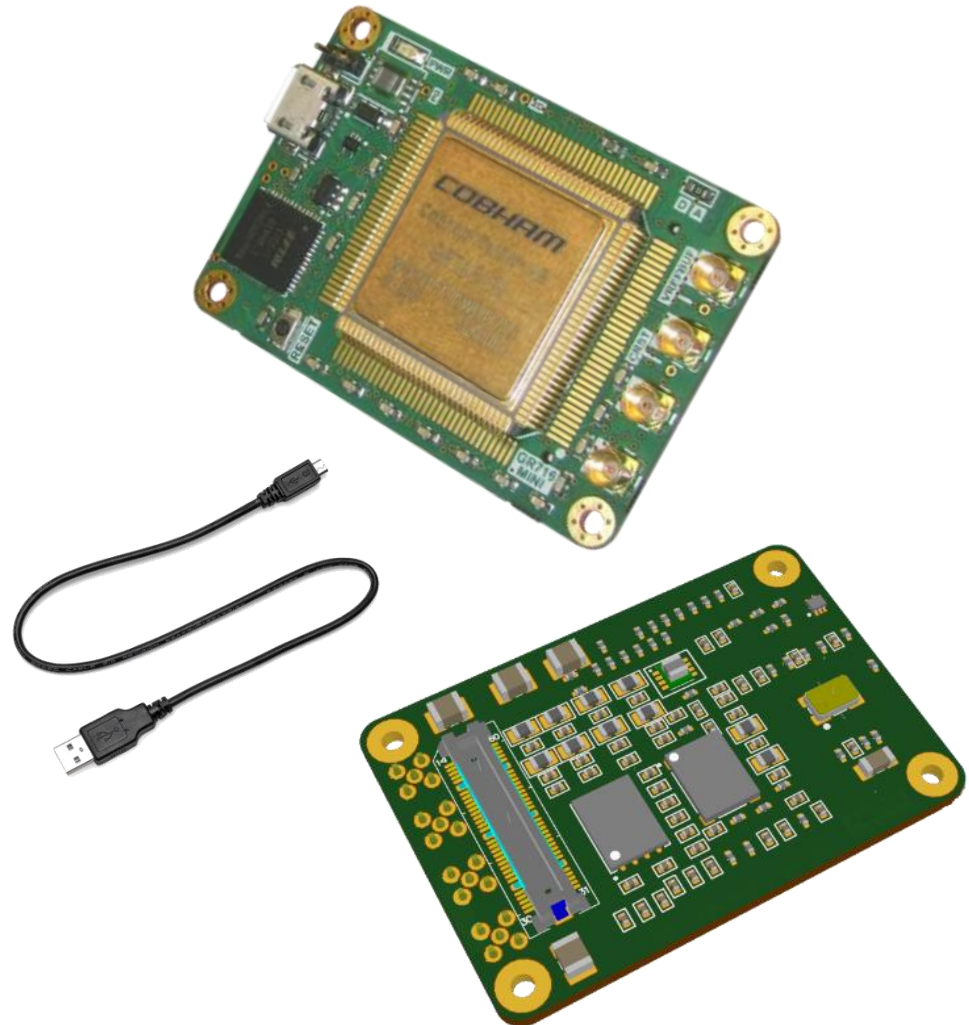


*Input frequency extended range
PLL*

GR716 evaluation board

GR716-MINI – GR716 Software evaluation board

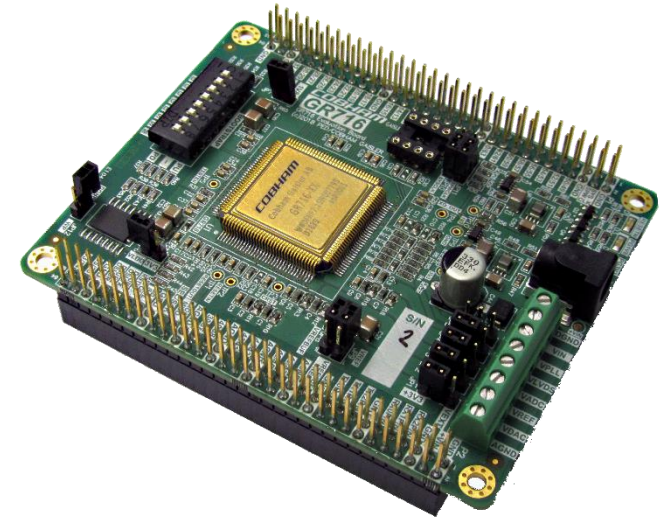
- Baseline design for evaluation board:
 - GR716 microcontroller
 - SPI Flash PROM (32 MiB)
 - SRAM (2 MiB)
 - FTDI USB interface
 - GRMON3 debug I/F via Debug UART
 - 2x UART interfaces, 1x I2C interface
 - control of reset, configuration pins etc.
 - power supply
 - 4x MMCX (micro-miniature coaxial):
 - 2x ADC, 2x DAC
 - miniature 80 pin mezzanine connector:
 - addition ADC, DAC, LVDS, GPIO, etc.
 - Oscillator
 - LED for power indication etc.
 - 50mm x 35mm (37.5% of a credit card)
- Shipped with:
 - free GRMON3 GUI (limited) download
 - free compilers, OS, tools downloads
 - USB cable (debug and power)



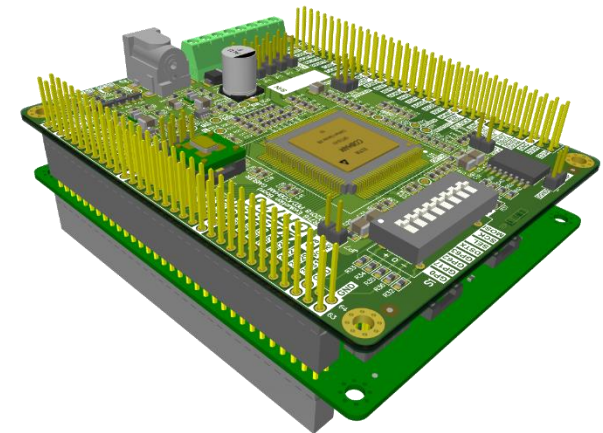
GR716 development board

GR716-BOARD – GR716 Hardware engineering board

- Baseline design for development board:
 - GR716 microcontroller
 - SPI Flash PROM (32 MiB)
 - PCI104 style stackable headers (2 x 64 pin) for interfaces
 - measurement points on all GPIO/interface signals for monitoring/debug
 - interface to user defined modules (memory, digital I/F, analog I/F)
 - interface to cPCI mother board in 6U rack or box format
 - Debug UART /IF
 - LVDS in/out (3+3 pairs) for 1x SpW or x SPI for Space
 - GPIO (64 pins)
 - digital I/O
 - external memory I/F
 - 6x UART
 - Mil-Std-1553B, PacketWire, CAN, I2C, 3x SPI, 16x PWM out
 - 8x analog in, 4x analog out, external ADC/ADC interface
 - 1x SpaceWire, 1x TDP
 - Socketed oscillator (5–25MHz)
 - DIP-switch for bootstrap options
 - Powered from external supply (range 5V to 12V)
 - Single supply operation or individual supplies
 - 80mm x 100mm format



GR716 Standalone Board

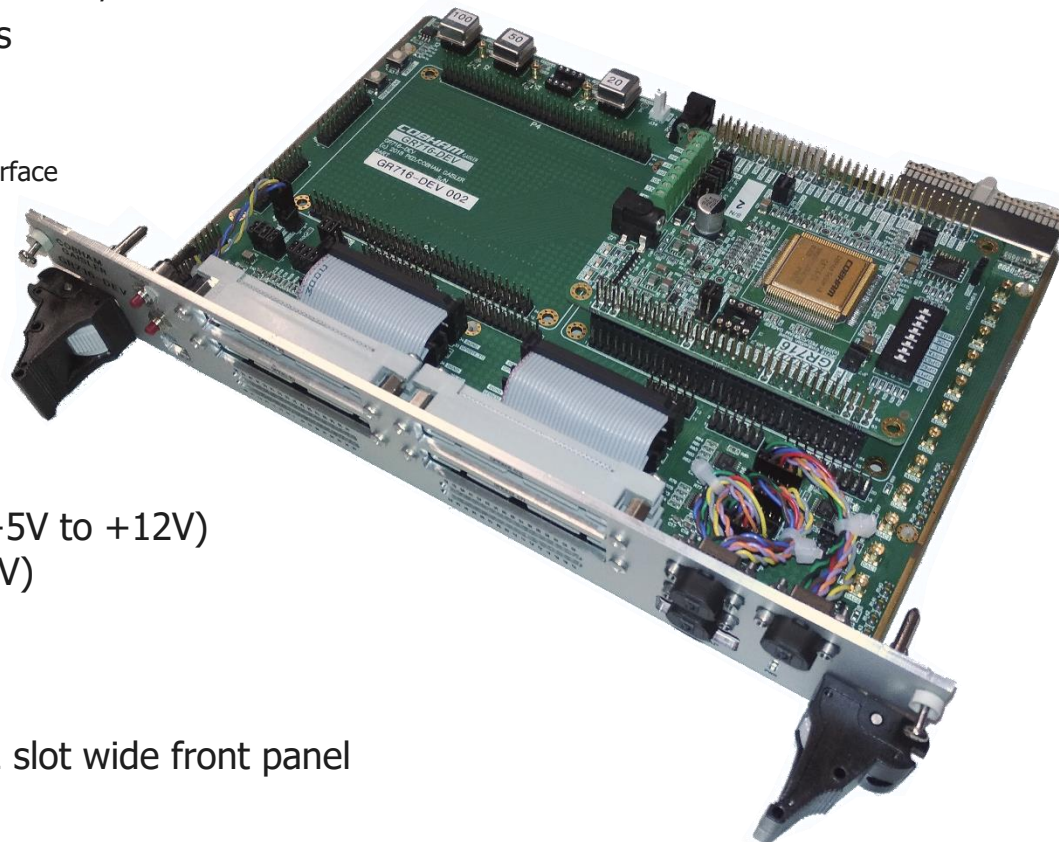


Stack multiple boards via PC104 connector

GR716 development board

GR-CPCI-GR716-DEV – GR716 interface development board

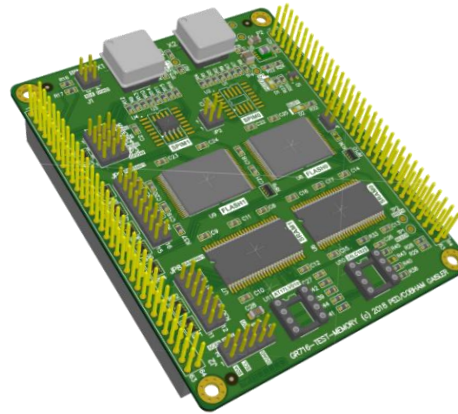
- Baseline design for interface application board:
 - GR716-BOARD engineering board in dedicated slot
 - Multiple slots for possibility to attach multiple GR716 engineering boards
 - Expansion slot for memory or user defined functions (e.g. SRAM, ADC/DAC)
 - Socketed oscillators for system, SpaceWire, Mil-Std-1553B and PWM clocks
 - Configuration of front panel functions
 - Front panel interfaces
 - MDM9S for fixed SpW (LVDS) interface
 - MDM9S for configurable SpW/SPI4S (LVDS) interface
 - GPIO (64 pins on standard 0.1" connectors)
 - LED indicators (64) for GPIO pins
 - DIP switch for bootstrap options
 - Reset and DSU Break push-button switches
 - LEDs for power and reset status
 - FTDI USB interface
 - GRMON3 debug I/F via Debug UART
 - 2x UART interfaces, 1x I2C interface
 - Power from external supply (range +5V to +12V) or via cPCI backplane connector (+5V)
 - Expansion through accessory boards
 - 6x UARTs using GR-CPCI-6U-UART
 - CAN, Mil-Std-1553B, SPI using GR-CPCI-GR740
 - 233mm x 160mm, 6U cPCI format, 2 slot wide front panel



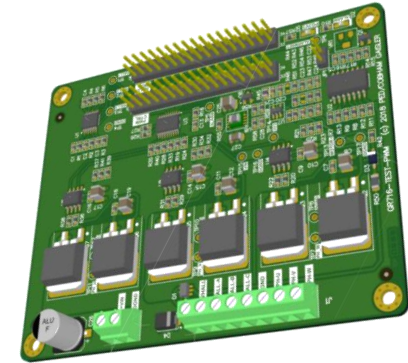
GR716 development board

GR716-BOARD – Extension-, Test- and Configuration- boards

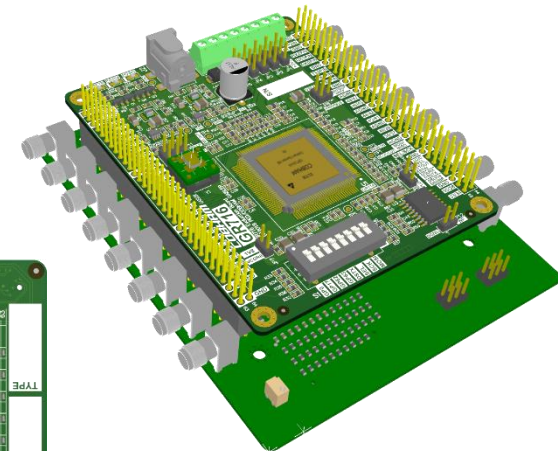
- GR716 Memory Board:
 - Memory extension board
 - Support dual memory redundancy protection
 - PCI104 style stackable headers (2 x 64 pin)
 - 80mm x 100mm format
- GR716 Configuration Board
 - Configuration board
- GR716 Analog Test Board
 - Interface board for analog interfaces
 - PCI104 style stackable headers (2 x 64 pin)
 - 80mm x 100mm format
- GR716 BLDC Test board
 - 3-phase inverter with PWM interface for interfacing BLDC/Stepper Motor



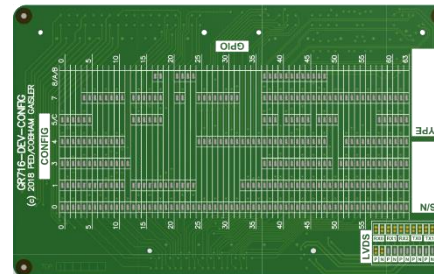
Memory Board



BLDC Test Board



Analog Test Board

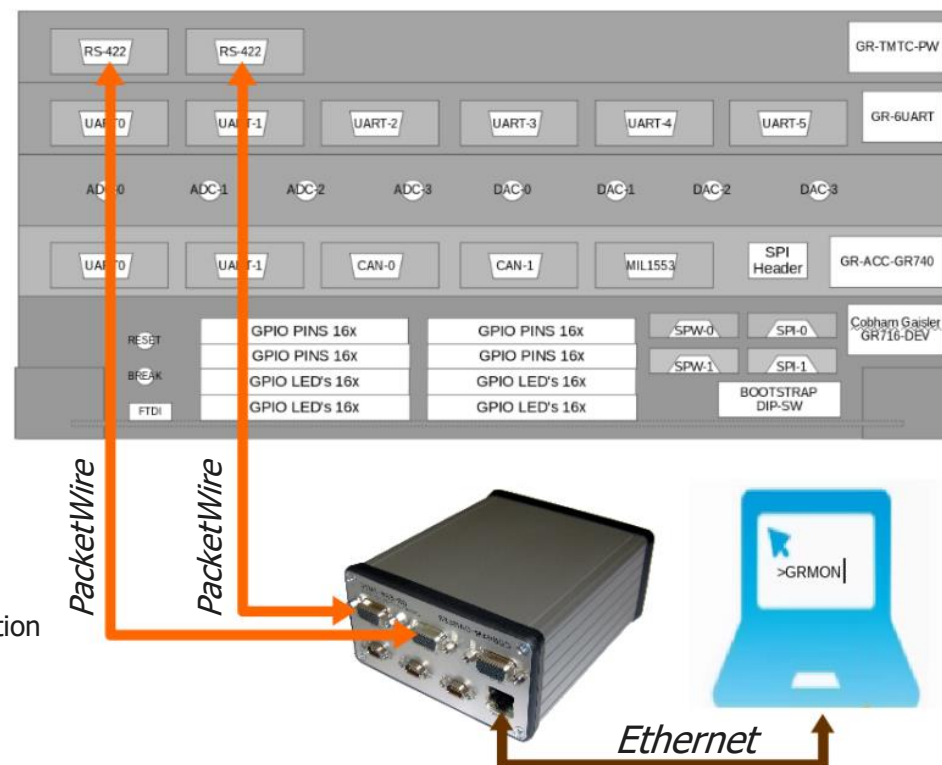


Configuration Board

GR716 development board

Build your application

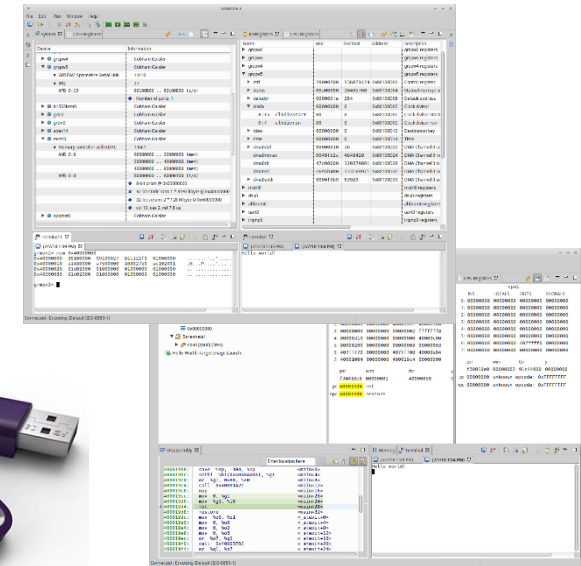
- Build your application via available interface boards
- Compatible boards possible to direct connect and use from Cobham Gaisler:
 - GR-ACC-6U-6UART
 - Extend number of UARTs in the system
 - GR-ACC-GR740
 - Dual CAN 2.0 transceiver, Dual MIL-1553B interface and SPI interface
 - GR-CPCI-CAN
 - Dual CAN 2.0 transceiver
 - GR-TMTC-PW (6U)
 - RX/TX PacketWire interface
 - SPI4S Test Board
 - Reference board for SPI for Space demonstration
 - Analog Front end
 - Easy connection of external ADC and DAC
- Use Configuration Board to avoid driver contamination
 - Possible to fit mezzanine board on the development board to avoid erroneous configuration of the IOs



GR716 Development Platform

GR716 software development environment

- BCC2 Development Environment
 - GCC 7.2.0 or CLANG 8.0.0
 - Performance increase with *'link time optimization'*
 - CLANG 8.0.0 to be released in 2018
 - GR716 BSP Support build in
- GRMON3 Debugger
 - Graphical User Interface (GUI) based on Eclipse TCF (Target Communication Framework) platform (used by Wind River and Xilinx)
 - GRMON displays HW/SW state in GUI without GDB in-between
 - **Low cost limited GR716 versions**
- TSIM3 Software Simulator
 - GR716 BETA release in 2019 Q1



- Bare metal toolchain for LEON processors
 - C/C++ cross compilers, both GCC and LLVM/Clang
 - C/C++ standard libraries
 - Open source with permissive licenses
- Support for GR716
 - Basic support for the GR716 architecture
 - Memory map, interrupts, capabilities
 - Linker scripts
 - ROM resident images
 - Support for GR716 features
 - REX
 - Single Vector Traps
 - Can generate chip specific instructions
 - Device drivers for GR716 I/O cores
 - Flat mode, staying in one register window
 - Can reduce jitter
 - Can be used with register window partitioning
 - Optional C runtime with even smaller footprint: -qnano

GR716 Development Platform

BCC2 for GR716 - Adjusting to different profiles

Property	Performance	Footprint	IRQ Response time
Soft mul/div	-	-	+
Soft float	-	-	+
Flat mode	*	-	+
Single Vector Trapping	-	+	-
Smaller runtime: -qnano		+	~
More register windows	+	~	~
IRQ jitter reduction	-	~	-
REX		+	
Optimize for size	-	+	~

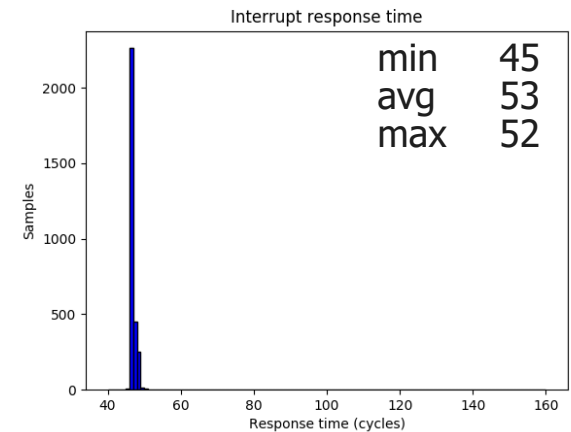
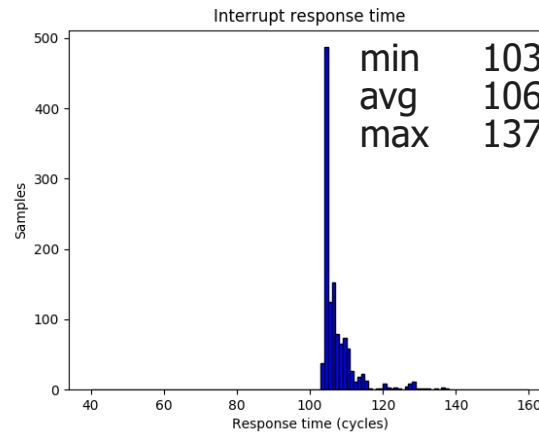
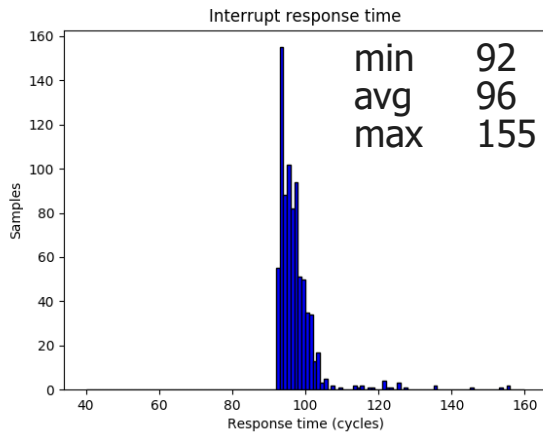
Effects in general for the given metric:

- + better
- worse
- ~ marginal
- * Varies

GR716 Development Platform

BCC2 for GR716 - Adjusting to different profiles - Whetstone

Performance mode	Footprint mode	Response time mode
8 s execution time	12 s execution time	250 s execution time
131 KiB footprint	77 KiB footprint	155 KiB footprint



- This is taking most parameters to the extreme end
 - No REX here in footprint mode
- Effects are application specific
- BCC2 Options can be mixed and matched to suit the application
- Footprints is excluding needed stack space

* Whetstone Profile Performance: GR716 run-time profiles Application note is available upon request via support@gaisler.com

- Already used in daily internal testing
 - All boot possibilities
 - Load and run from local memory or external SRAM
 - Many of the new GR716 features in place
- TSIM-GR716 BETA release in 2019 Q1
 - In between TSIM2 and TSIM3
 - GR716 does not need all new features of TSIM3
 - User model API available
 - Not in final TSIM3 form

TSIM

```
$ /tsim-leon3 -gr716 ./coremark.elf
tsim> run

TSIM/LEON3 SPARC simulator, version tsim3-dev-ad71c1e55f1cee67 (internal version)

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For latest updates, go to http://www.gaisler.com/
Comments or bug-reports to support@gaisler.com

Number of CPUs: 1
register windows: 31
system frequency: 50.000 MHz
using 64-bit time
Allocated 128 KiB LOCAL ICACHE RAM memory at 0x31000000
Allocated 64 KiB LOCAL DCACHE RAM memory at 0x30000000
allocated 4096 KiB SRAM memory, in 1 bank
allocated 2048 KiB ROM memory
allocated 16384 KiB SPIM ROM memory
allocated 16384 KiB SPIM ROM memory
section: .text, addr: 0x31000000, size 78032 bytes
section: .rodata, addr: 0x30000000, size 3088 bytes
section: .data, addr: 0x300000c10, size 1584 bytes
read 475 symbols
tsim> run
  starting at 0x31000000
2K performance run parameters for coremark.
CoreMark Size   : 666
Total ticks     : 18529354
Total time (secs): 18.529354
Iterations/Sec  : 107.936844
Iterations      : 2000
Compiler version: GCC7.2.0
Compiler flags  : -O2 -qnano -qsvt -qbsp=gr716 -mcpu=leon3
Memory location : Static
seedcrc        : 0xe9f5
[0]crlst       : 0xe714
[0]crcmatrix   : 0x1fd7
[0]crcstate    : 0x8e3a
[0]crcfinal    : 0x4983
Correct operation validated. See readme.txt for run and reporting rules.
CoreMark 1.0 : 107.936844 / GCC7.2.0 -O3 -qnano -qsvt -flto -qbsp=gr716 -mcpu=leon3 / S

Program exited normally.

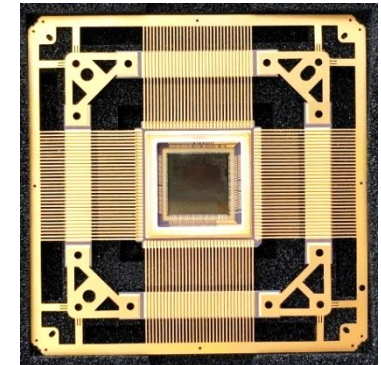
tsim>
```

GR716 updated schedule

As of 12 December 2018

GR716	Status	Milestone	Comments
Advanced Data Sheet & User's Manual	done	Q2 2017	Available
PDR	done	Q2 2017	review passed in June
CDR	done	Q2 2018	review passed in May
Prototype level tape-out	done	Q2 2018	taped-out in May
Prototype level assembly	done	Q3 2018	completed in September
Prototype level functional test	done	Q4 2018	completed in December
Prototype level performance test		Q1 2019	Ongoing
Prototype level part delivery		Q1 2019	Ongoing
Evaluation board delivery		Q1 2019	Ongoing

- GR716 microcontroller is funded by ESA up to prototype design and validation, output from ESA activity will be prototype parts and evaluation boards.
- Additional funding available from ESA for the evaluation with respect to analogue performance and radiation.
- Qualification decision pending successful evaluation.
- Price list to be established and orders for prototypes to be accepted in Q1 2019.



Highlights

- Successfully developed and integrated several new digital and RadHard analogue IP cores in first tape-out
- Successfully taped-out and demonstrated working prototypes
- Successfully manufactured system development kit
- Improved LEON-SPARC tool-chain and debugger released
- Improved the LEON3FT code density and real-time characteristics
 - LEONREX
 - Fast context switching
- Improved work flow:
 - ESD strategy for mixed signal ASIC
 - Voltage drop strategy
 - Low power strategy
 - SET strategy
 - Digital on top integration and verification

Preliminary performance results

- All ADC and DAC channels are working
 - ADC linearity less than 1 LSB
 - DAC linearity less than 5 LSB *
- BandGap voltage reference is measured to 1.003V and external voltage reference to 2.40V.
- Single voltage supply and separate voltage supply has been validated
- Possible to trim the internal core voltage from software in range 1.780V to 1.925V.
- Crystal Oscillator, PLL and frequency generation logic has been validated
 - Sleep and low-power mode
- Possibility to trim and set BrownOut detection levels has been validated
- Power on reset functionality has been validated
- Glitch free GPIOs during power-up or power-down **

** Limitation in test setup. (1 LSB = 1 μ A)*

*** Test system not able to detect any glitches lower than 1 μ A.*

- Mixed signal microcontroller prototypes has been successfully manufactured
- Microcontroller characteristics implemented
 - High level of integrated RadHard analogue functions
 - High level of integrated digital functions and communications interface
 - High level of configurability
 - Scalable performance
 - Software debugger and toolchain with driver and device support
- Microcontroller suitable for variety of platforms and equipment

THANK YOU FOR LISTENING!

Contact support@gaisler.com for more information